

Garda-3 Block Diagram

(Discrete)

CLK GEN.

IDT CV125PA
(ICS 954206) 3

Mobile CPU

Yonah 478

G791/G792

19

Project code: 91.4P401.001

PCB P/N : 55.4P401.XXX

REVISION : 06208-2

(Hannstar, GCE)

DATE:2006/07/??

PCB STACKUP

TOP
VCC
S
S
GND
BOTTOM

SYSTEM

TPS51120

40

INPUTS

OUTPUTS

DCBATOUT

5V_S5
3D3V_S5

SYSTEM DC/DC

APL5912

43

INPUTS

OUTPUTS

1D8V_S3

1D05V_S0

TPS51116

41

DCBATOUT

1D8V_S3
DDR_VREF_S0

APL5332KAC

3D3V_S0

2D5V_S0

43

APL5912

1D8V_S3

1D5V_S0

43

MAXIM CHARGER

ISL6255

42

INPUTS

OUTPUTS

DCBATOUT

CHG_PWR
18V 4.0A

UP+5V

5V 100mA

CPU

ISL6262

38,39

INPUTS

OUTPUTS

DCBATOUT

VCC_CORE_S0

0~1.3V

44A

ATI M52 DC/DC

ISL6269

52

INPUTS

OUTPUTS

DCBATOUT

VGA_CORE_S0

APL5331

43

1D8V_S0

1D2V_S0

BOM

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

BLOCK DIAGRAM

Size

A3

Document Number

AG3

Rev

2

Date: Thursday, April 20, 2006

Sheet 1 of 55

A

B

ICH7M Integrated Pull-up
and Pull-down Resistors

ICH7-M EDS 17837 1.5V1

EE_DIN,EE_DOUT, GNT[3:0], GPIO[25], GNT[4]#/GPIO48, GNT[5]#/GPO17, PME#, LAD[3:0]#/FHW[3:0]#, LAN_RXD[2:0]	ICH7 internal 20K pull-ups
LDRQ[0], LDRQ[1]/GPIO[41], PWRBTN#, TP[3]	
DD[7], DDREQ	ICH7 internal 11.5K pull-downs
ACZ_BIT_CLK, ACZ_RST#, ACZ_SDIN[2:0], ACZ_SDOUT,ACZ_SYNC, DPRSLPVR/GPIO16, EE_CS,SPI_ARB, SPI_CLK, SPKR,	ICH7 internal 20K pull-downs
USB[7:0][P,N]	ICH7 internal 15K pull-downs
SATALED#	ICH7 internal 15K pull-up
LAN_CLK	ICH7 internal 100K pull-down

3

ICH7M IDE Integrated Series
Termination Resistors

DD[15:0], DIOW#, DIOR#, DREQ, DDACK#, IORDY, DA[2:0], DCS1#, DCS3#, IDEIRQ	approximately 33 ohm
--	----------------------

ICH7M Functional Strap Definitions

page 16

Signal	Usage/When Sampled	Comment
ACZ_SDOUT	XOR Chain Entrance/ PCIE Port Config bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low.When TP3 not pulled low at rising edge of PWROK,sets bit1 of RPC.PC(Config Registers: offset 224h)
ACZ_SYNC	PCIE bit0, Rising Edge of PWROK.	Sets bit0 of RPC.PC(Config Registers:Offset 224h)
EE_CS	Reserved	This signal should not be pull high.
EE_DOUT	Reserved	This signal should not be pull low.
GNT2#	Reserved	This signal should not be pull low.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT5#/ GPIO17#, GNT4#/ GPIO48	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT5# is MSB, 01-SPI, 10-PCI, 11-LPC.
DPRSLPVR	Reserved	This signal should not be pull high.
GPIO25	Reserved. Rising Edge of RSMRST#.	This signal should not be pull low.
INTVRMEN	Integrated VccSus1_05 VRM Enable/Disable. Always sampled.	Enables integrated VccSus1_05 VRM when sampled high
LINKALERT#	Reserved	Requires an external pull-up resistor.
REQ[4:1]#	XOR Chain Selection. Rising Edge of PWROK.	TBD, Chapter 8.
SATALED#	Reserved	This signal should not be pull low.
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH7 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.

C

954305D 27Mhz/LCDCLK Spread
and Frequency Selection Table

SS3 Byte9 bit 7	SS2 bit6	SS1 bit5	SS0 bit4	Spread Amount%
0	0	0	0	-0.50 Down
0	0	0	1	-1.00 Down
0	0	1	0	-1.50 Down
0	0	1	1	-2.00 Down
0	1	0	0	-0.75 Down
0	1	0	1	-1.25 Down
0	1	1	0	-1.75 Down
0	1	1	1	-2.25 Down
1	0	0	0	+0.25 Center
1	0	0	1	+0.5 Center
1	0	1	0	+0.75 Center
1	0	1	1	+1.0 Center
1	1	0	0	+0.25 Center
1	1	0	1	+0.5 Center
1	1	1	0	+0.75 Center
1	1	1	1	+1.0 Center

page 3

PCI Routing

page 16

	IDSEL	INT -> PIRQ	REQ/GNT
1410	22	A->G	0
MiniPCI	21	A/C B/D -> E	1
LAN	23	A -> H	2
1394	17	A->B, B->F,	3

History

D

E

Calistoga Strapping Signals and
Configuration

EDS 17050 0.71

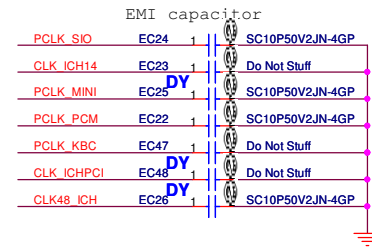
page 7

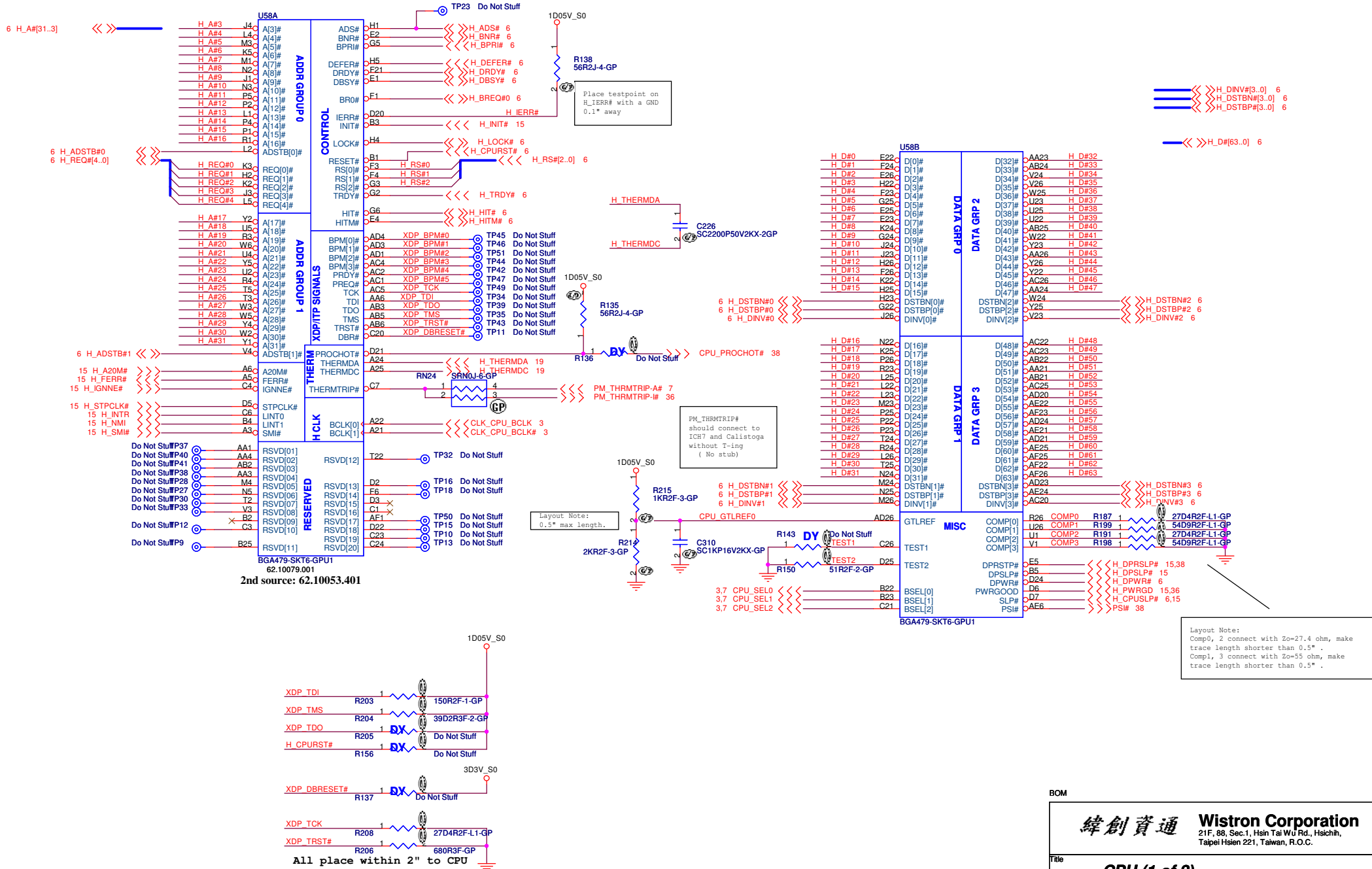
Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	001 = FSB533 011 = FSB667 others = Reserved
CFG[4:3]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG6	Reserved	
CFG7	CPU Strap	0 = Reserved 1 =Mobile CPU(Default)
CFG8	Reserved	
CFG9	PCI Express Graphics Lane Reversal	0 = Reverse Lanes,15->0,14->1 ect.. 1= Normal operation(Default):Lane Numbered in order
CFG[11:10]	Reserved	
CFG[13:12]	XOR/ALL Z test straps	00 = Reserved 01 = XOR mode enabled 10 = All Z mode enabled 11 = Normal Operation (Default)
CFG[15:14]	Reserved	Reserved
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG17	Global R-comp Disable (All R-comps)	0 = All R-comp Disable 1 = Normal Operation (Default)
CFG18	VCC Select	0 = 1.05V (Default) 1 = 1.5V
CFG19	DMI Lane Reversal	0 = Normal operation (Default):lane Numbered in order 1 =Reverse Lane,4->0,3->1 ect...
CFG20	SDVO/PCIE Concurrent	0 = Only SDVO or PCIE x1 is operational (Default) 1 =SDVO and PCIE x1 are operating simultaneously via the PEG port
SDVOCTRL _DATA	SDVO Present	0 = No SDVO Card present (Default) 1= SDVO Card present

NOTE: All strap signals are sampled with respect to the leading
edge of the Calistoga GMCH PWORK in signal.

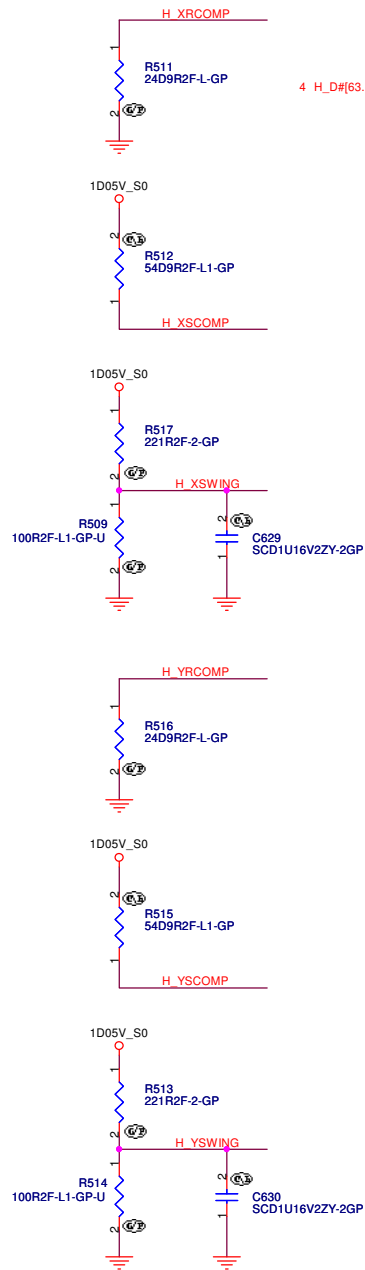
BOM

緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
Reference			
Size A3	Document Number AG3		Rev 2
Date: Thursday, April 20, 2006		Sheet 2 of	55

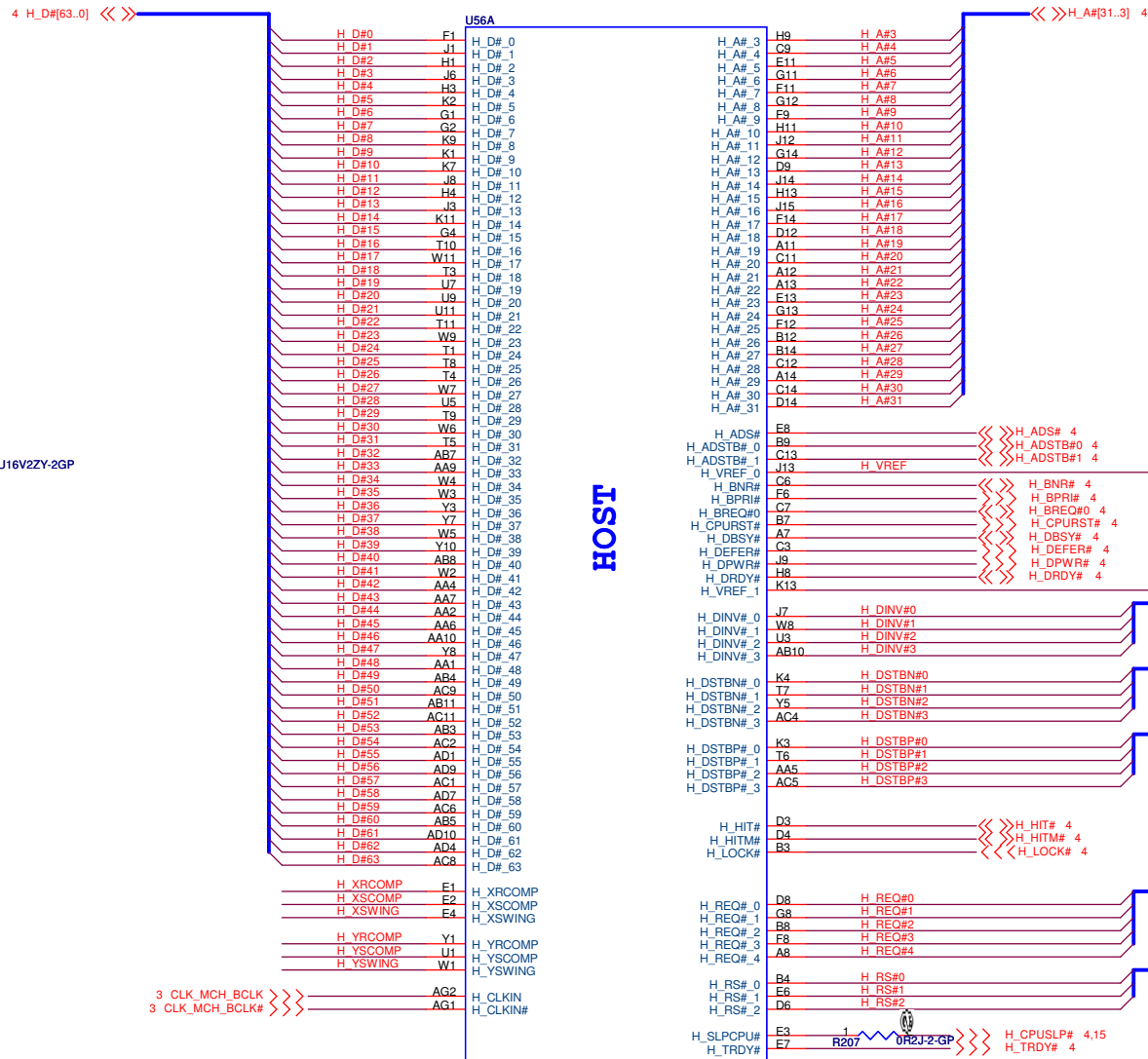




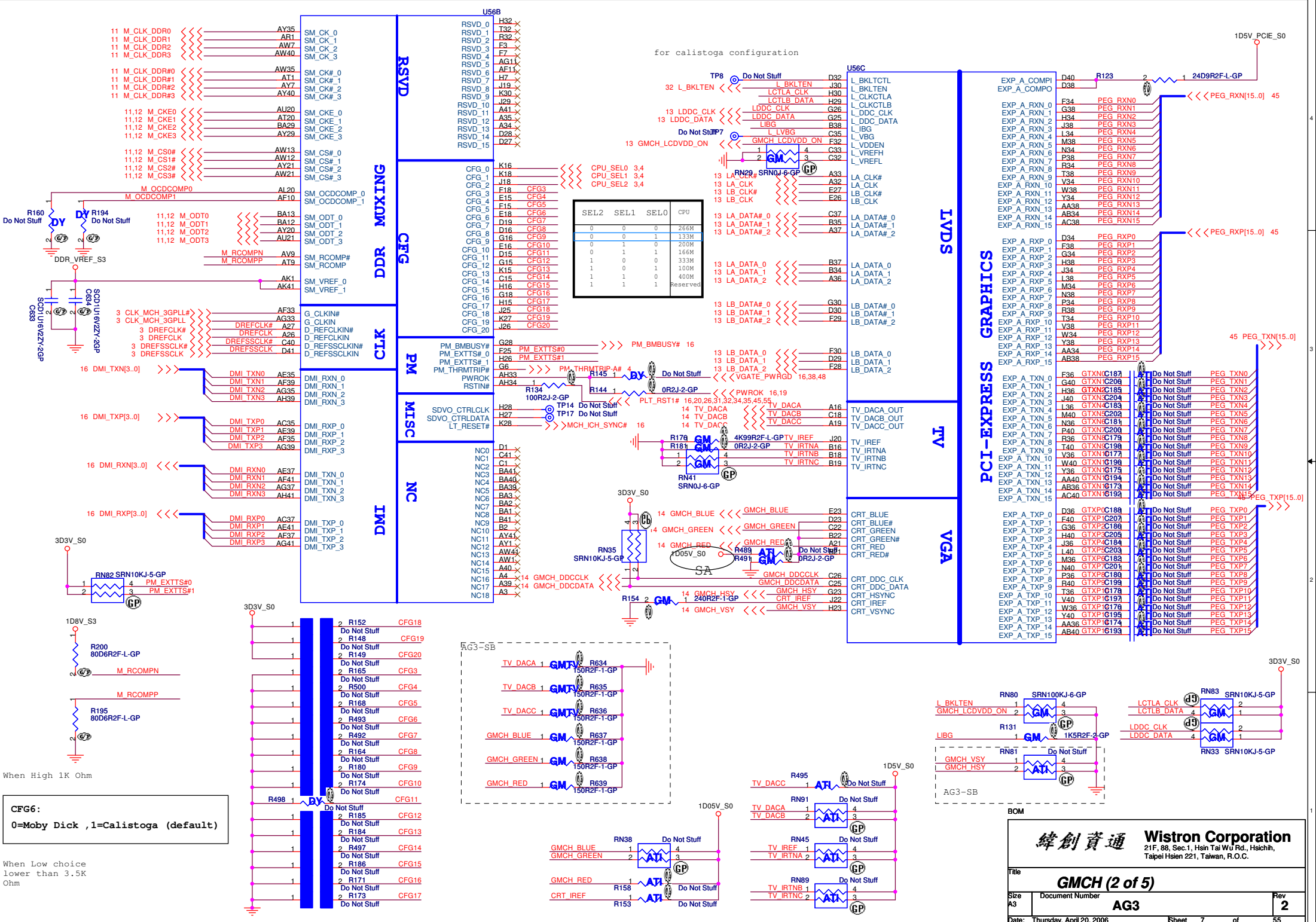


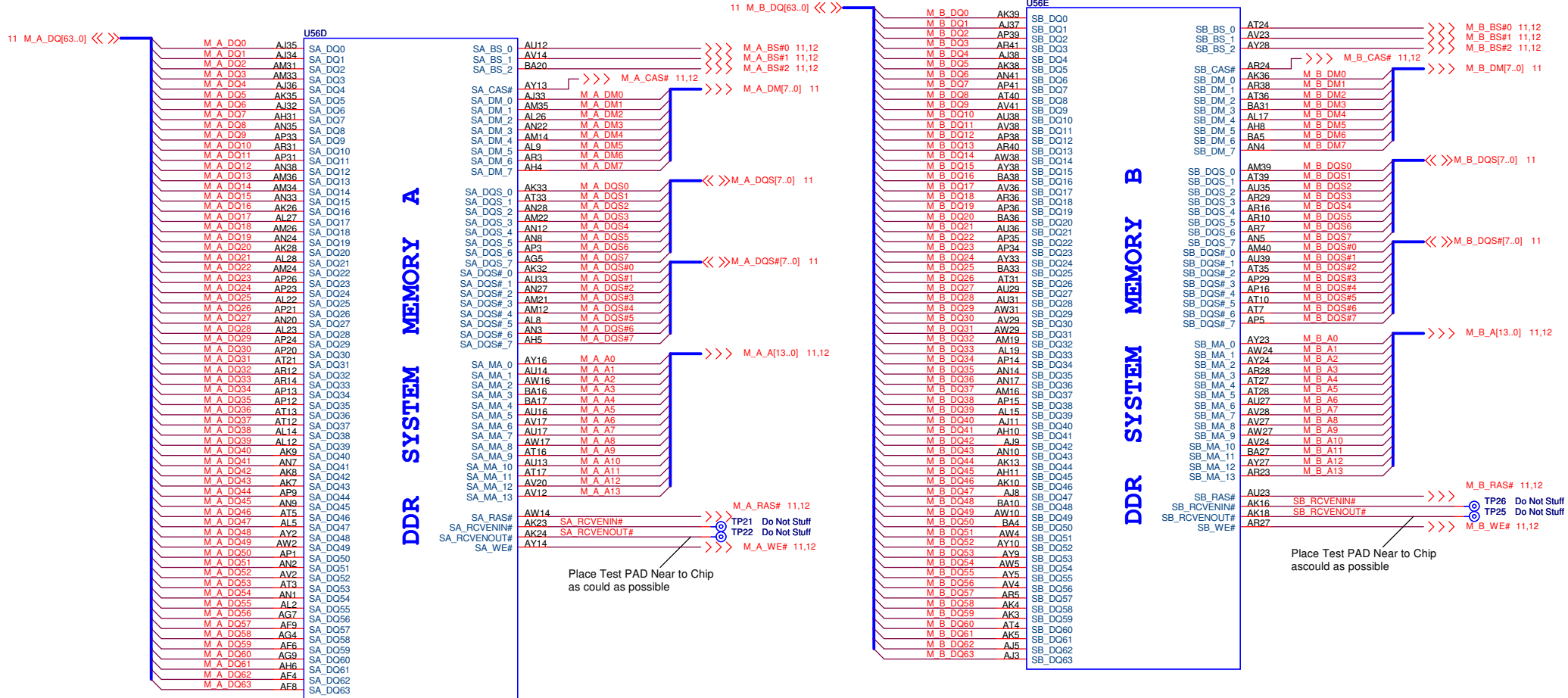


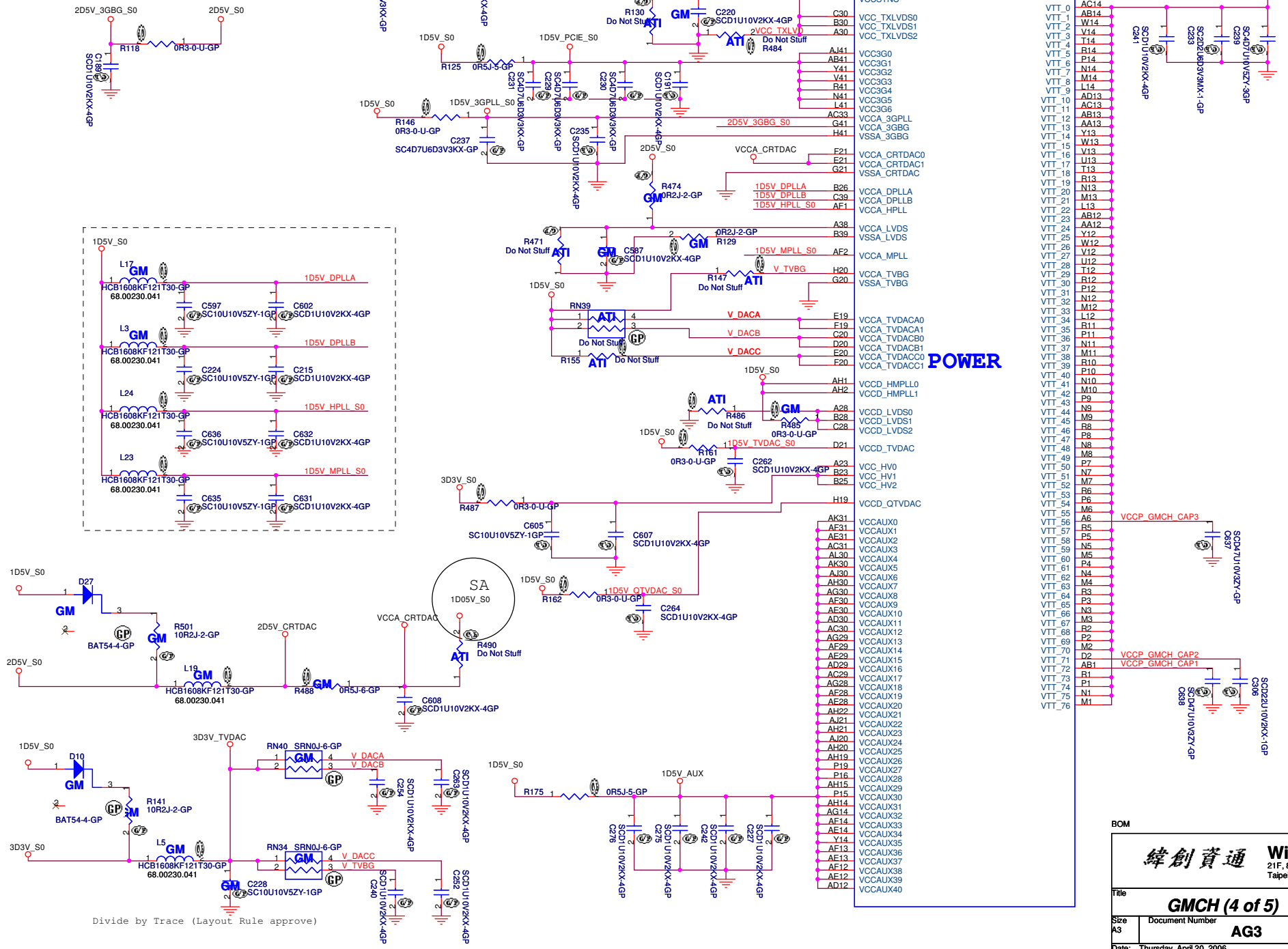
Place them near to the chip (< 0.5")



BOM



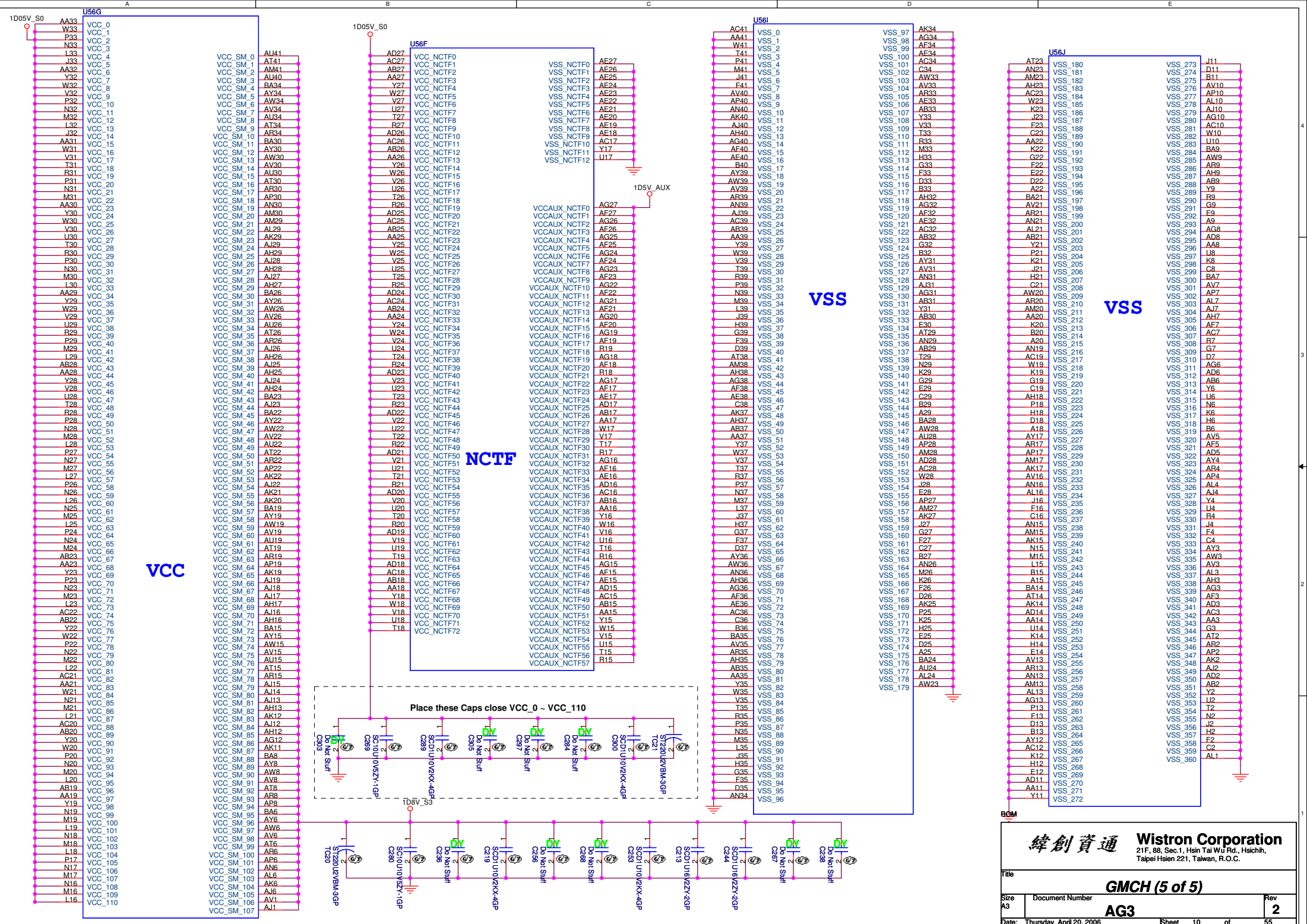




BOM

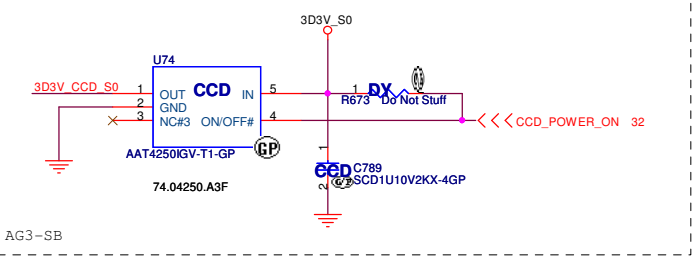
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsin 221, Taiwan, R.O.C.

File		
GMCH (4 of 5)		
Size	Document Number	Rev
A3	AG3	2
Date: Thursday, April 20, 2006		
Sheet 9 of 55		

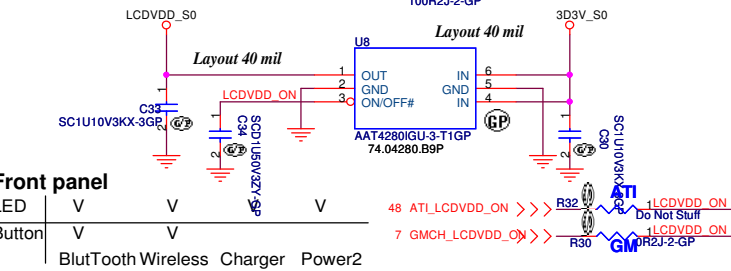
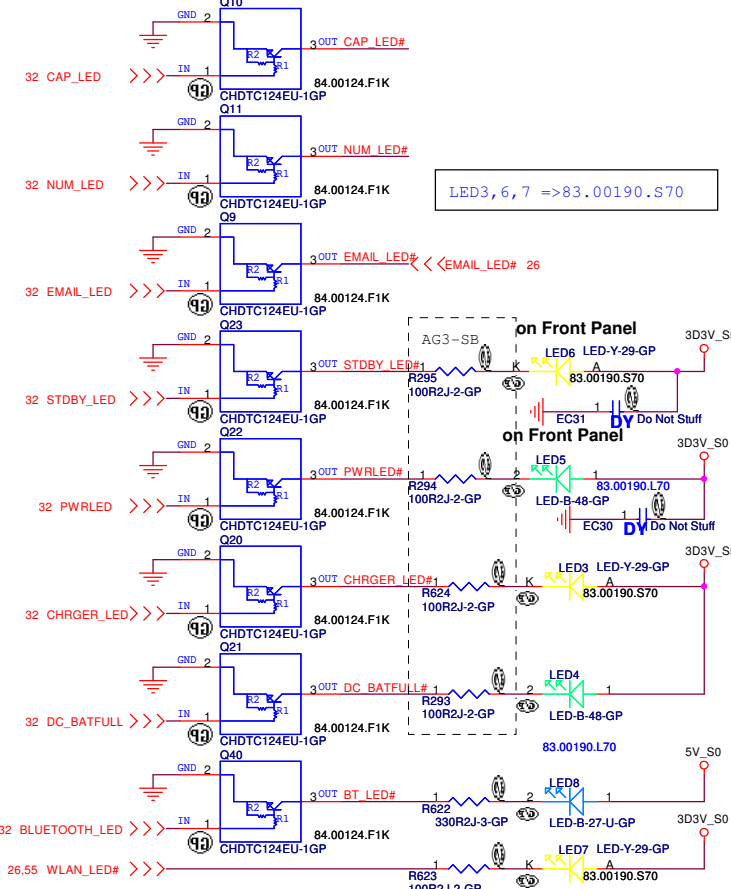


Put decap near power(0.9V) and pull-up resistor

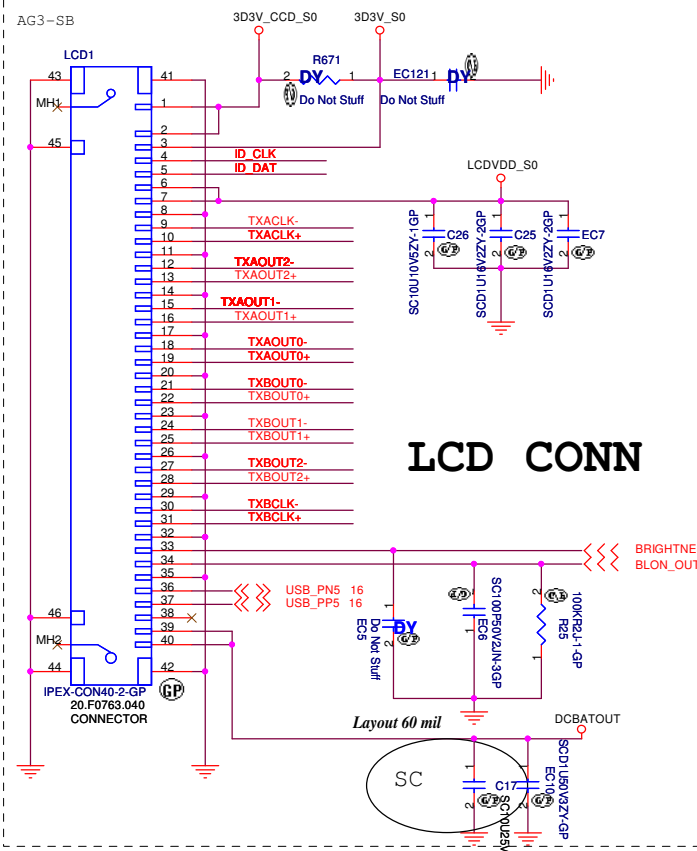
Title			
DDR2 Termination Resistor			
Size A3	Document Number		Rev
	AG3		2
Date:	Friday, April 21, 2006	Sheet 12 of	55



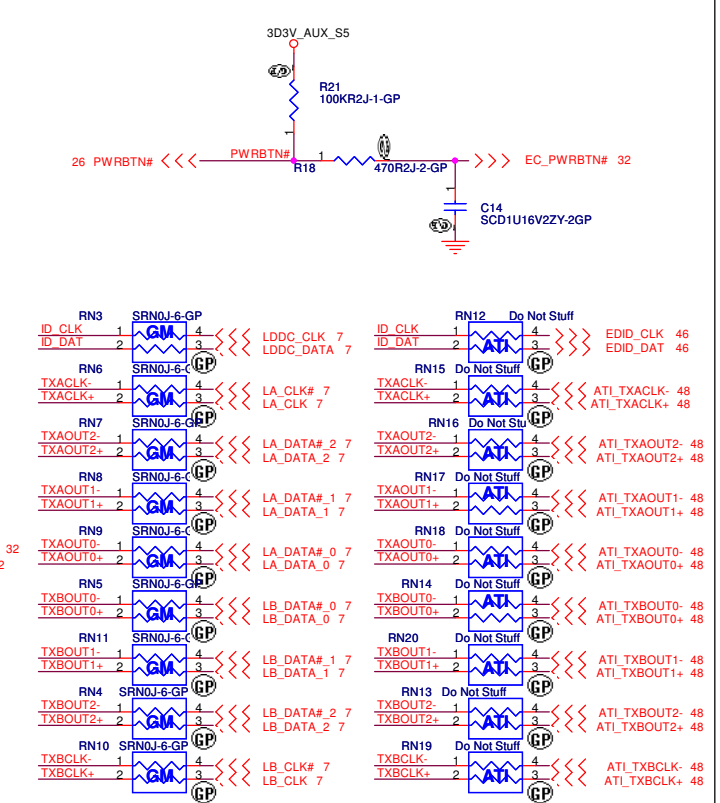
2nd source: 20.K0185.012



LED	V	V	V	V
Bluetooth	Wireless	Charger	Power2	



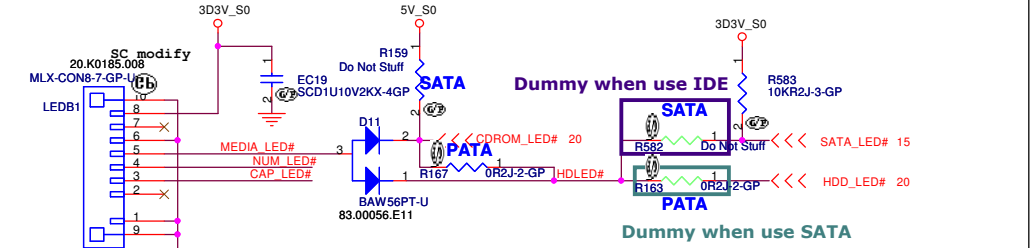
LCD CONN



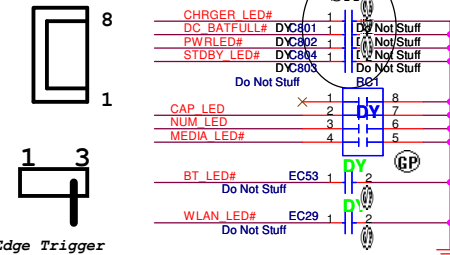
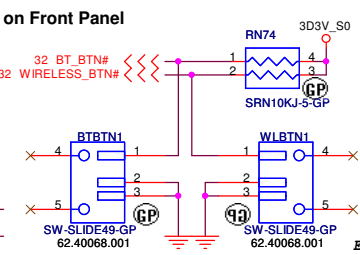
LED BD CONN

Charger:
 OFF : Battery or DC only
 Orange : Charging
 Orange Blink : Battery low

Power:
 Green : S0
 Orange : S3
 Orange Blinking : Enter S4



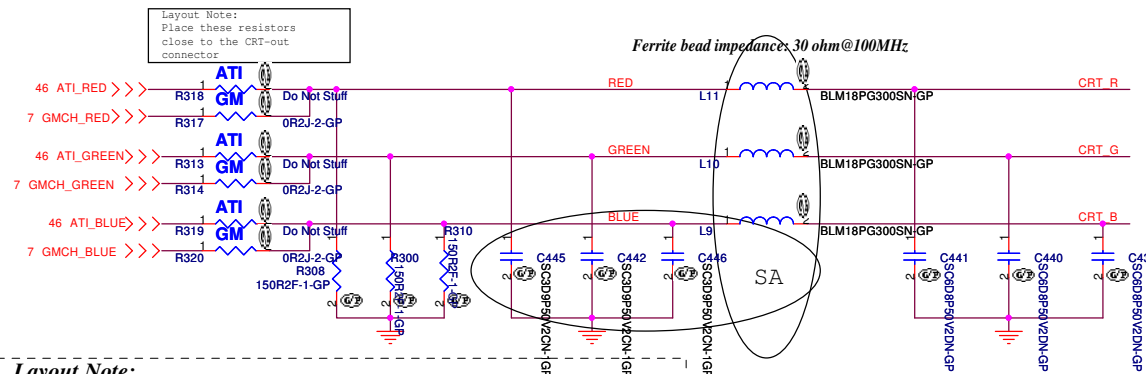
1st source: 20.K0228.008



BOM	
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
LCD / LAUNCH / LEDs	
Size	Document Number
A3	AG3
Date: Friday, April 21, 2006	Sheet 13 of 55
Rev 2	

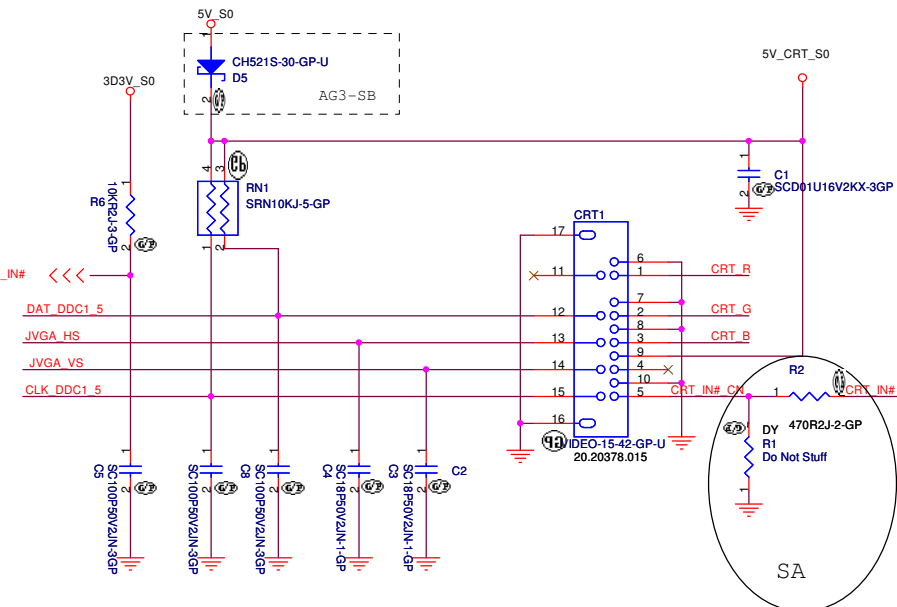
CRT I/F & CONNECTOR

Ferrite bead impedances 30 ohm@100MHz

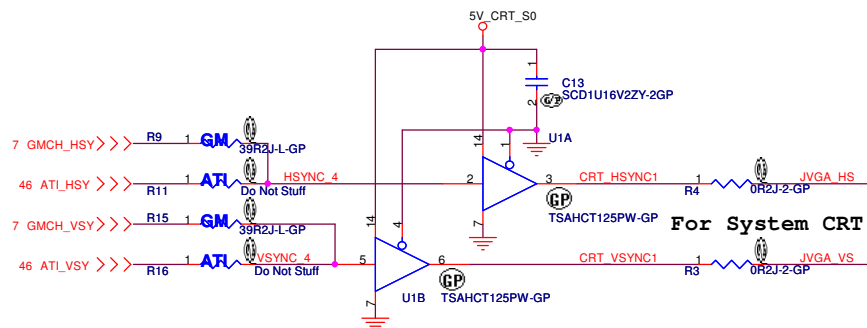


Layout Note:

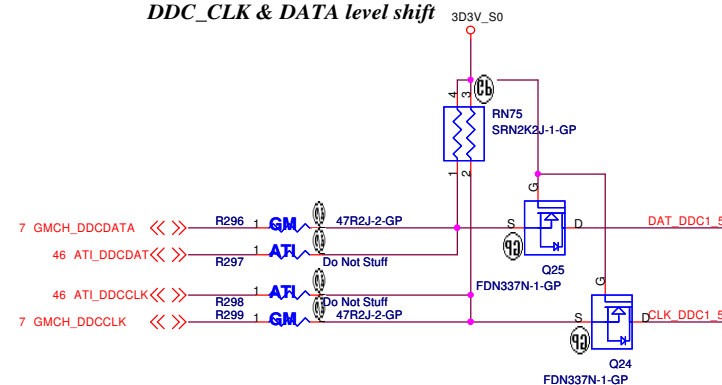
* Must be a ground return path between this ground and the ground on the VGA connector.
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.



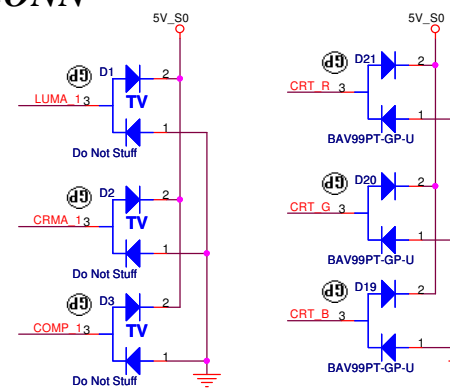
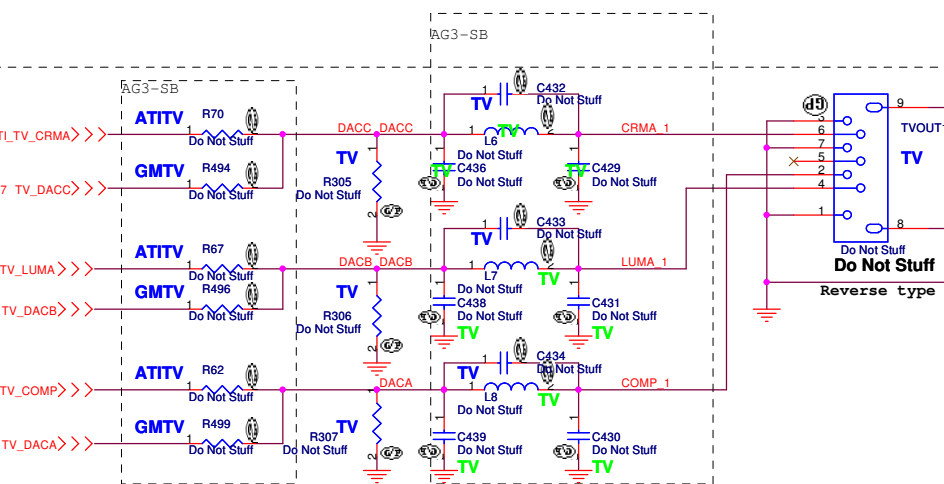
Hsync & Vsync level shift



DDC_CLK & DATA level shift



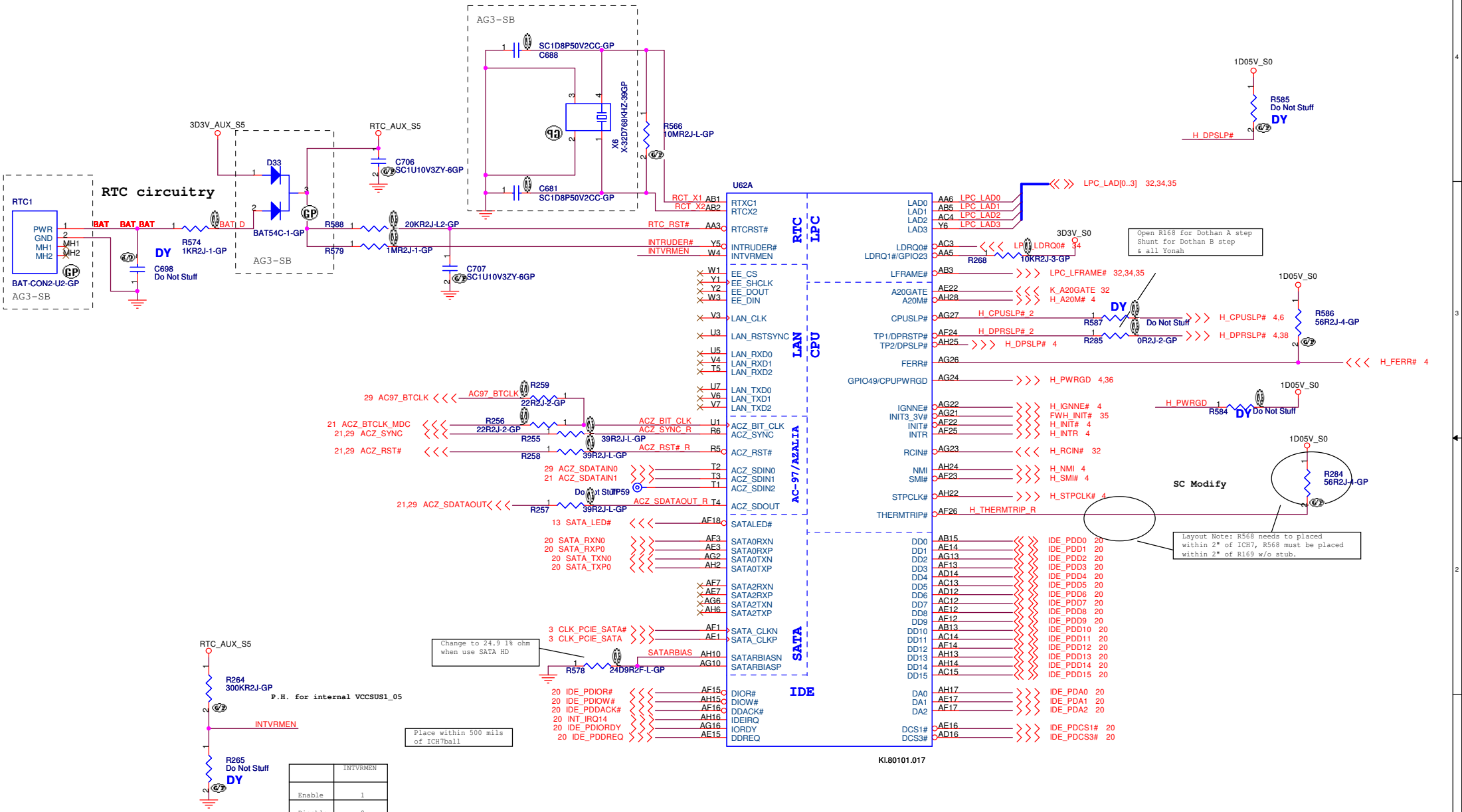
TV OUT CONN



BOM

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

CRT/TV Connector			
Size A3	Document Number	AG3	Rev 2
Date: Thursday, April 20, 2006	Sheet 14	of 55	



Placement Note:
Distance between the ICH-7 M and cap on the "P" signal should be identical distance between the ICH-7 M and cap on the "N" signal for same pair.

	INTVRMEN
Enable	1
Disable	0

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

ICH7-M (1 of 4)

Size

A3

Document Number

AG3

Date

Friday, April 21, 2006

Sheet

15

of

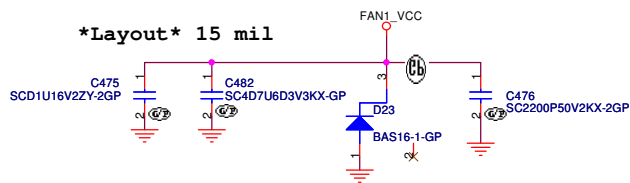
55

Rev

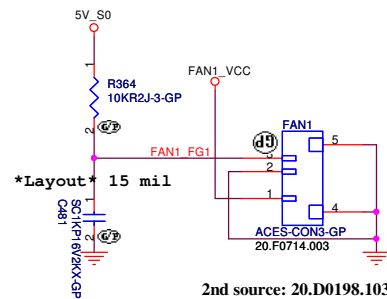
2

K1.80101.017

Layout 15 mil

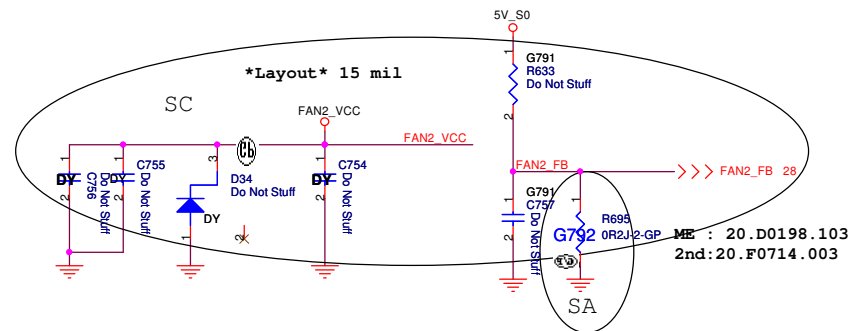


Layout 15 mil



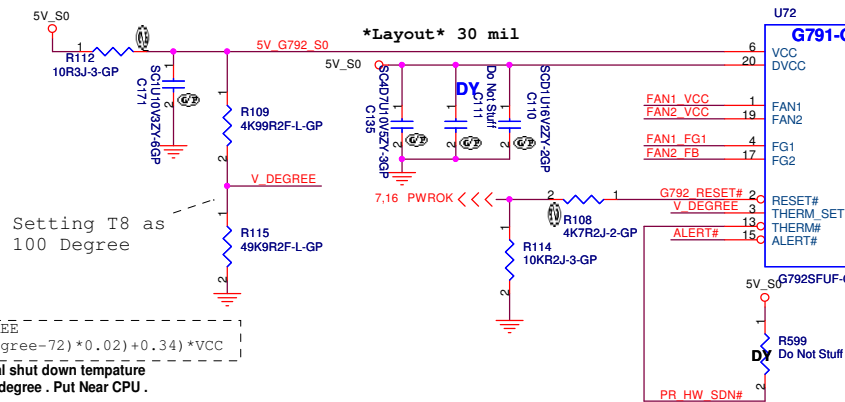
2nd source: 20.D0198.103

Layout 15 mil



ME : 20.D0198.103
2nd: 20.F0714.003

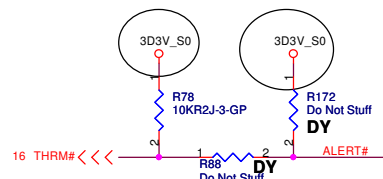
Layout 30 mil



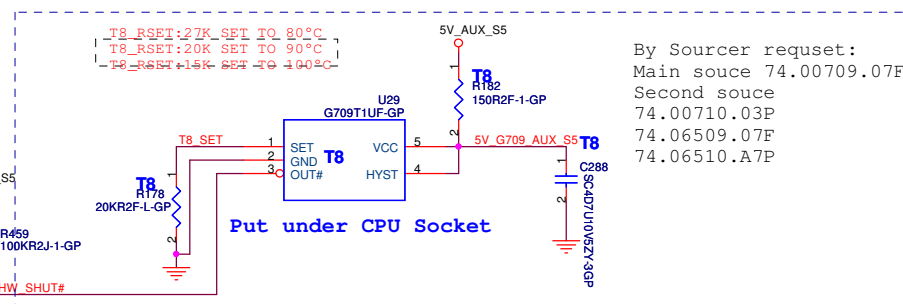
Setting T8 as
100 Degree

V_DEGREE
= (((Degree-72)*0.02)+0.34)*VCC
HW thermal shut down temperature
setting 95 degree . Put Near CPU .

DXP1:108 Degree
DXP2:H/W Setting
DXP3:88 Degree



32.36 PURE_HW_SHUTDOWN# <<<



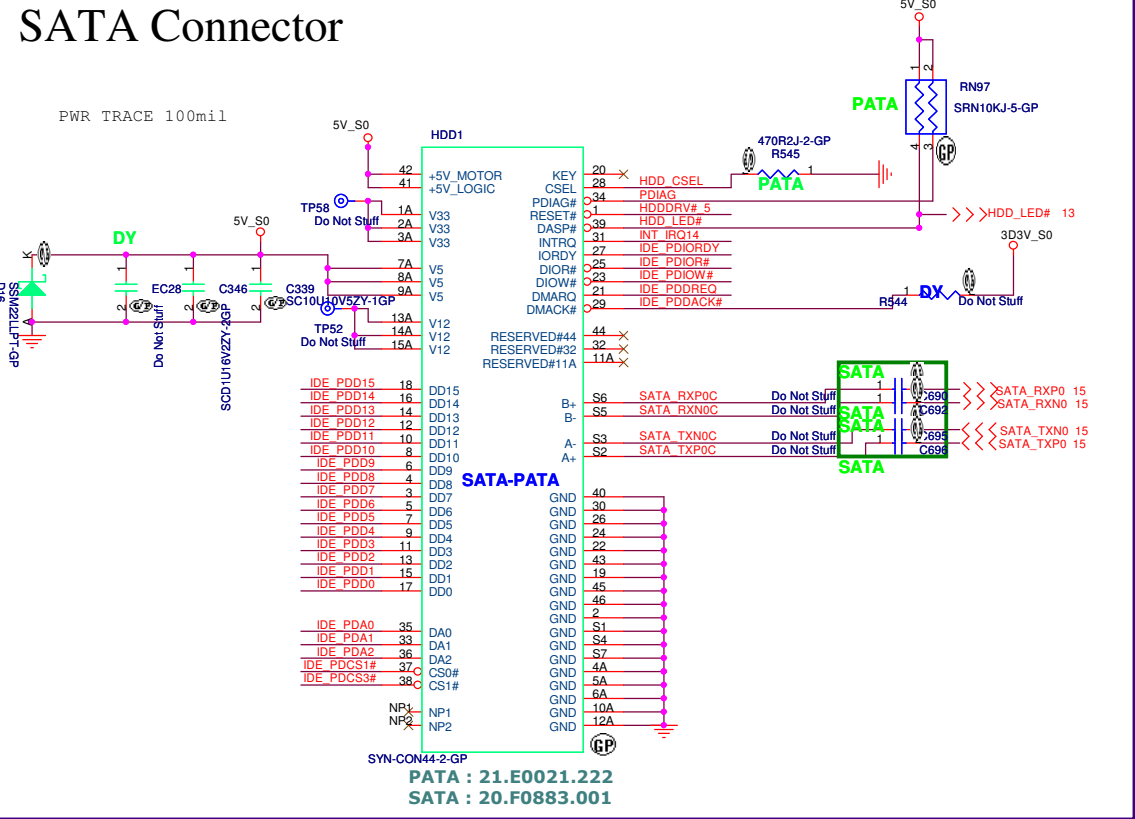
Put under CPU Socket

By Sourcer request:
Main souce 74.00709.07F
Second souce
74.00710.03P
74.06509.07F
74.06510.A7P

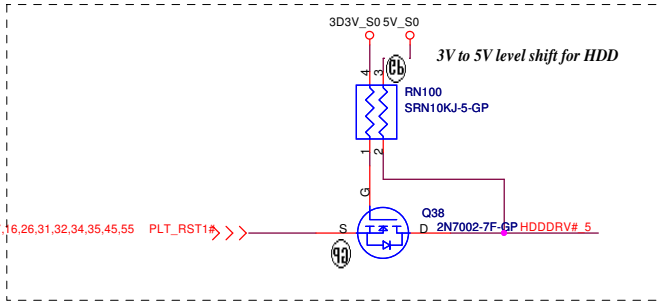
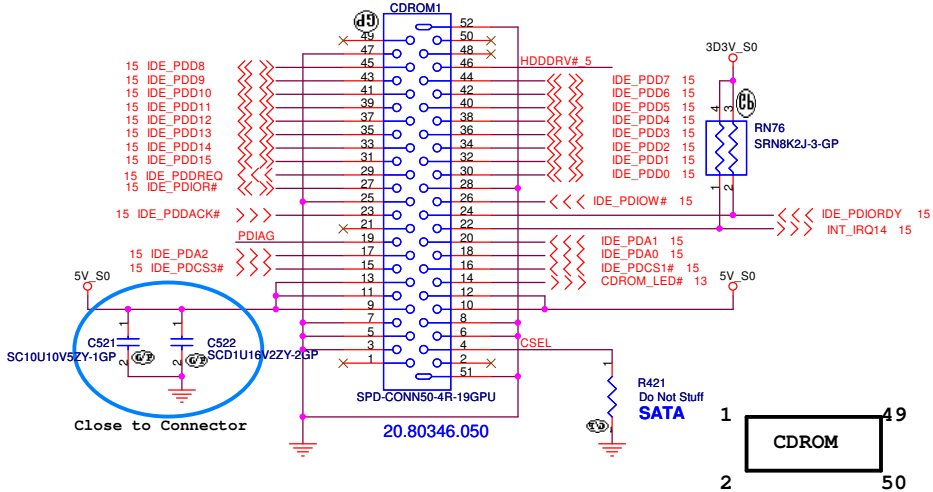
BOM

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Thermal/Fan Controller G792			
Size A3	Document Number AG3	Rev 2	
Date: Friday, April 21, 2006		Sheet 19	of 55

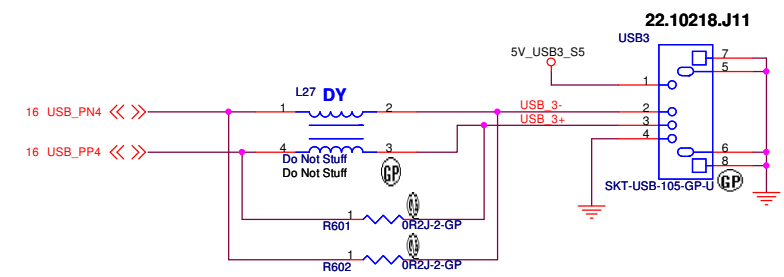
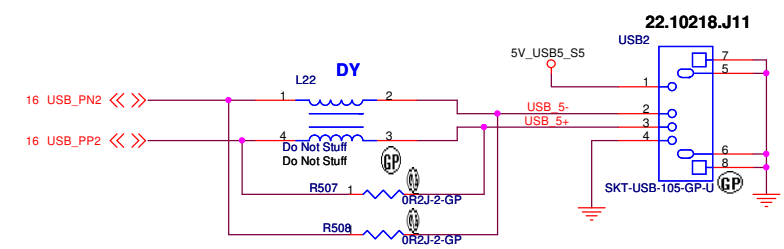
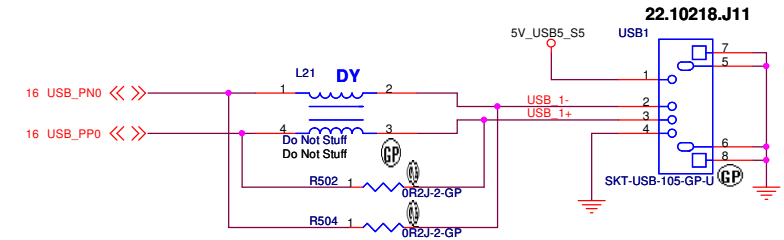
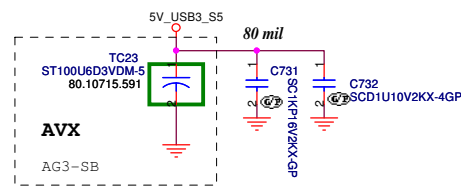
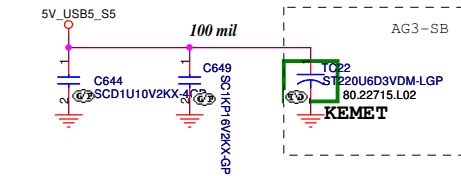
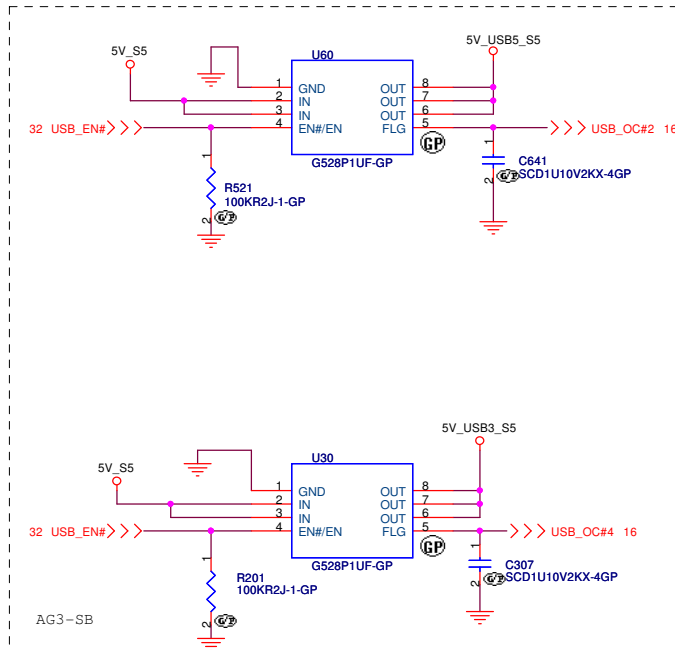
SATA Connector



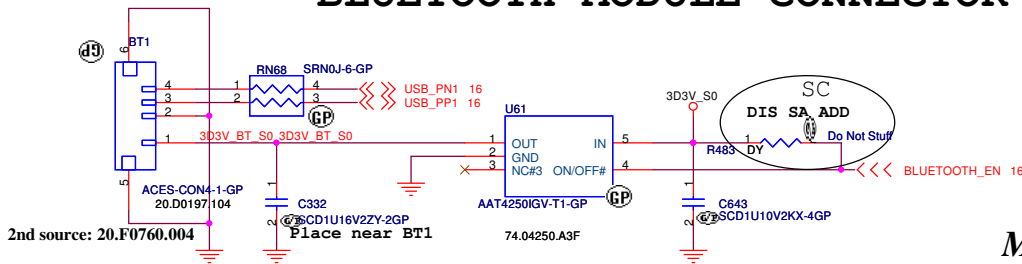
CDROM Connector



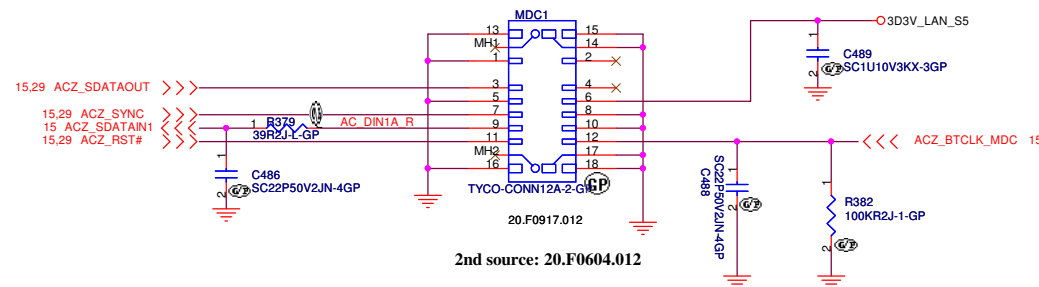
USB PORT



BLUETOOTH MODULE CONNECTOR



MDC 1.5 CONN



BOM			
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
USB and MDC I/F			
Size	Document Number	Rev	
A3	AG3	2	
Date:	Friday, April 21, 2006	Sheet	21 of 55



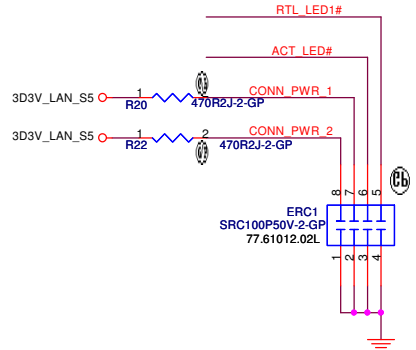
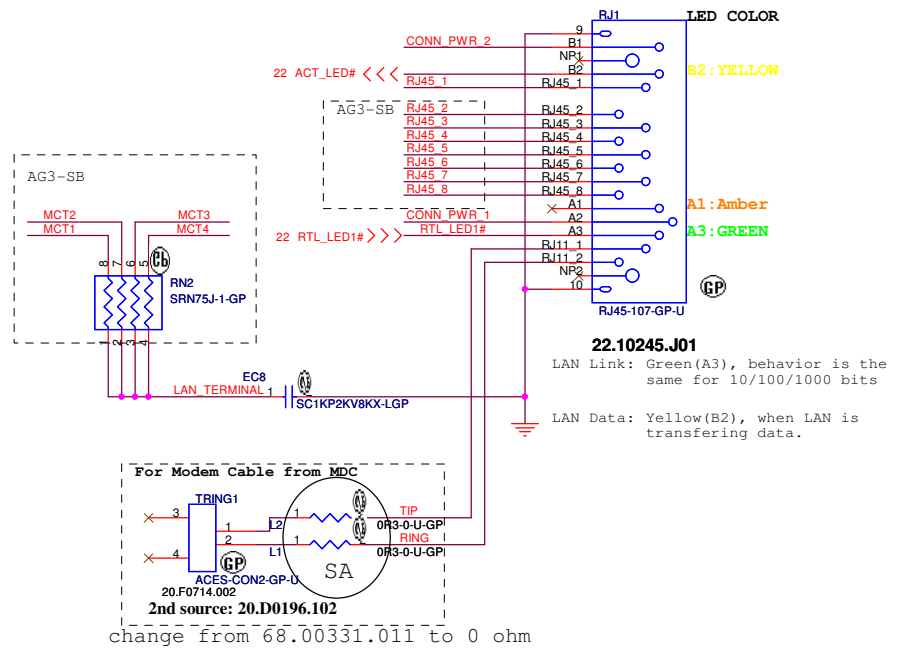
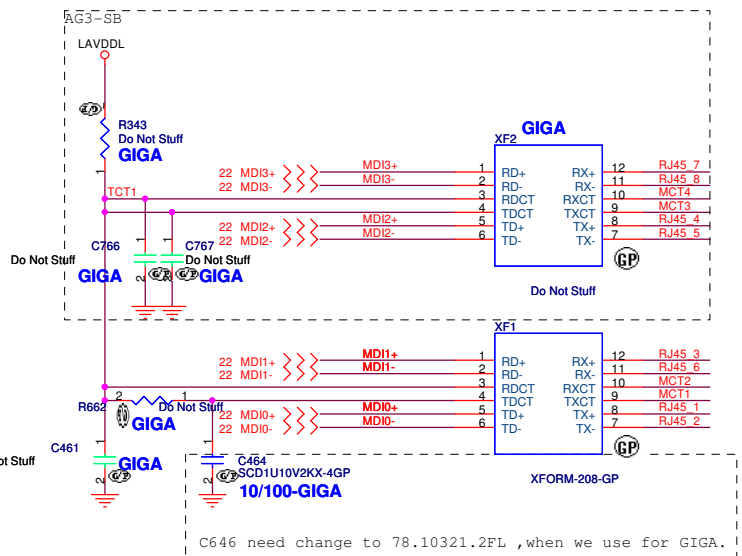
PIN NAME	8110SBL (Giga)	8100CL (10/100)	SIGNAL NAME
VDD33	3.3	3.3	3D3V_LAN_S5
AVDDH	3.3	N.C.	AVDDH
VDD18	1.2	2.5	DVDD
AVDD18	1.2	2.5	DVDD_A
AVDDL	2.5	3.3	AVDDL
V_12P	3.3	2.5	V_12P

- 1.route on bottom as differential pairs.
- 2.Tx+/Tx- are pairs. Rx+/Rx- are pairs.
- 3.No vias, No 90 degree bends.
- 4.pairs must be equal lengths.
- 5.6mil trace width,12mil separation.
- 6.36mil between pairs and any other trace.
- 7.Must not cross ground moat,except RJ-45 moat.

RJ11 signal must leave the other signal or power plane 100mil.

DOC_TIP,DOC_RING,TIP,RING:
W/S : 10/100 @ Surface layers
10/20 @ Inner layers

10/100 LAN Transformer	RJ45 PIN
TD+ --> TX+	RJ45-1
TD- --> TX-	RJ45-2
RD+ --> RX+	RJ45-3
RD- --> RX-	RJ45-6



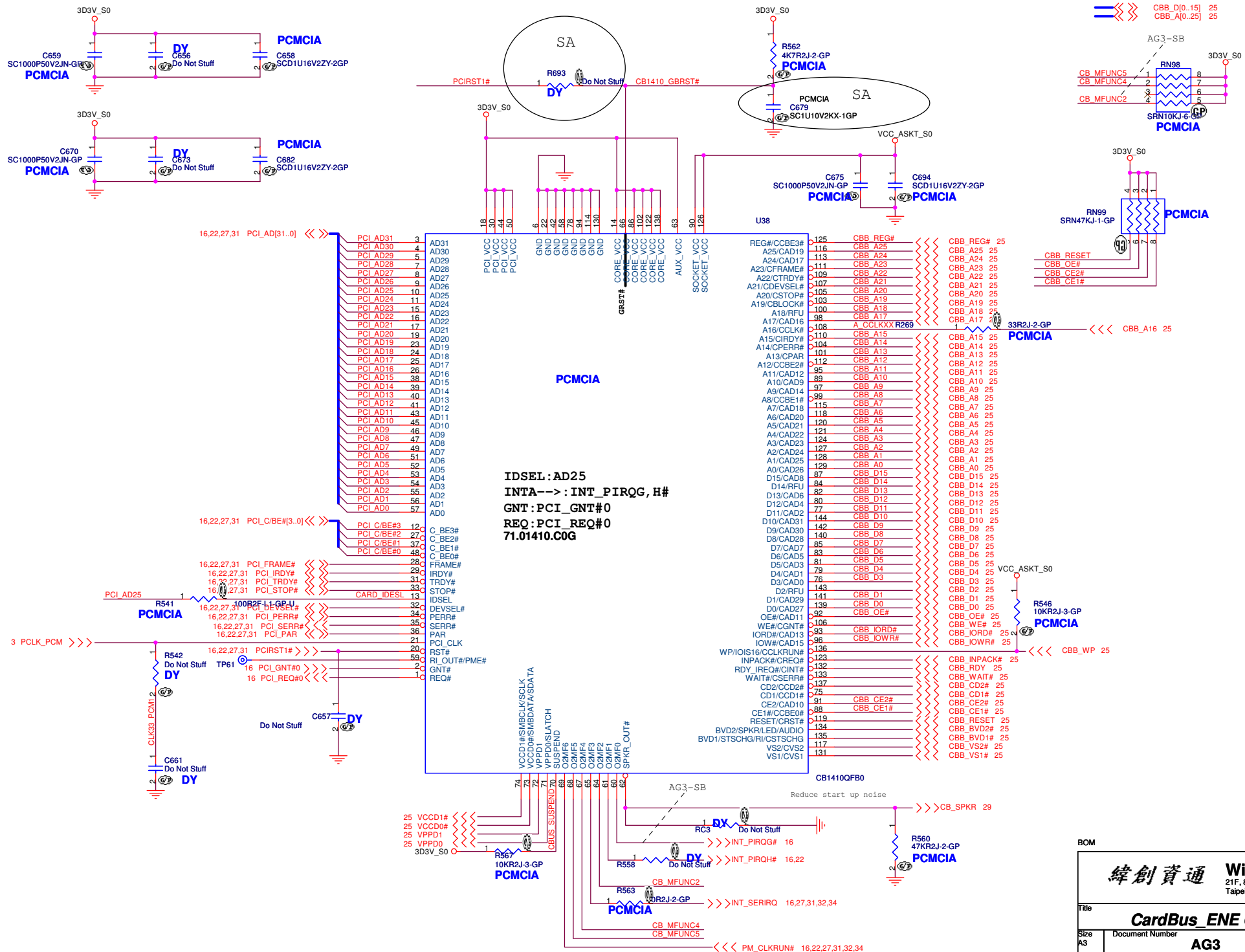
LAN Connector

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **LAN Connector**

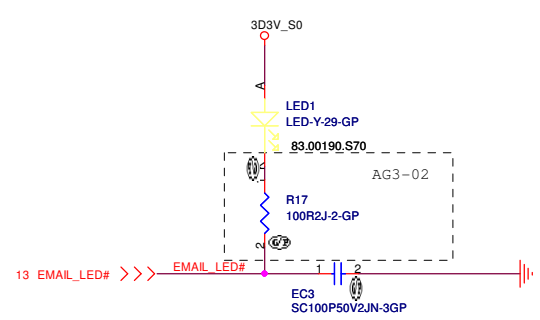
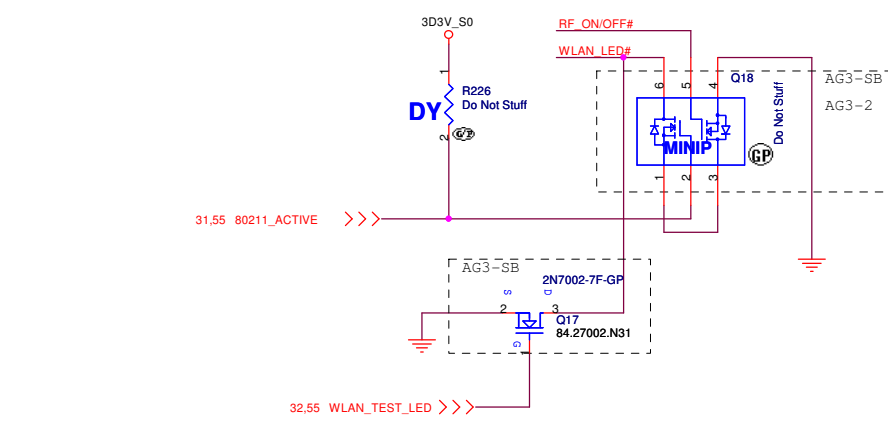
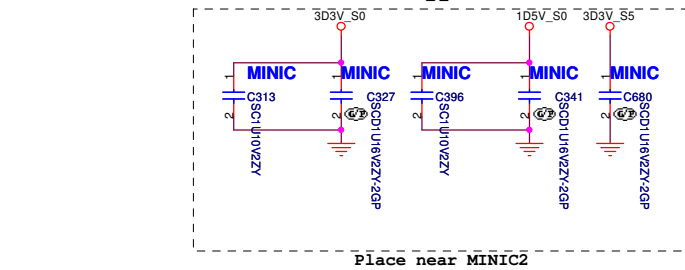
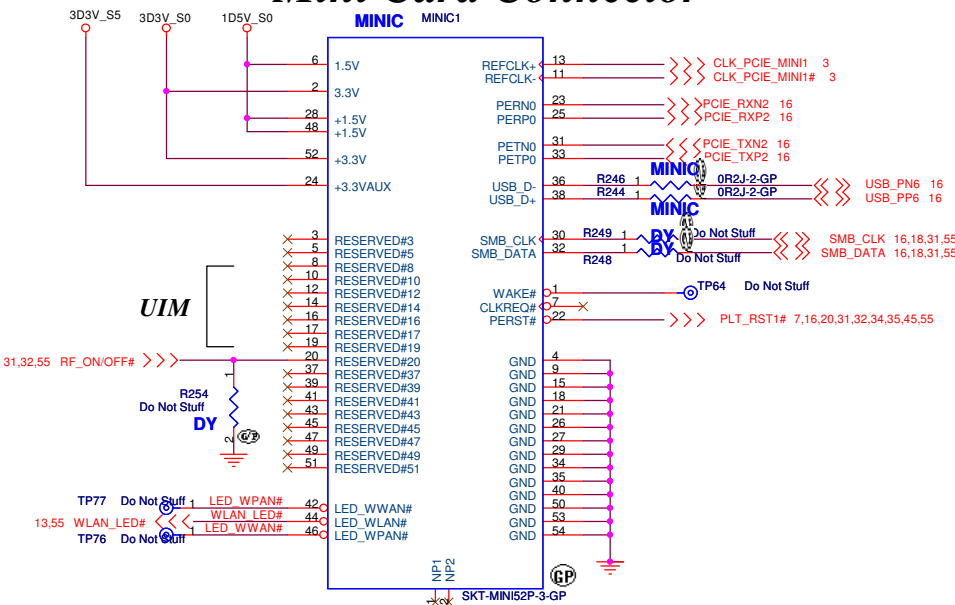
Size A3 Document Number: **AG3** Rev: **2**

Date: Thursday, April 20, 2006 Sheet 23 of 55

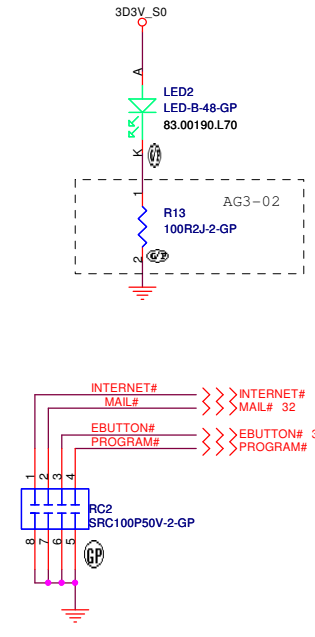
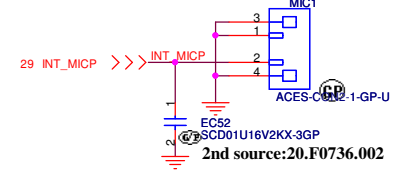


Title			
PCMCIA			
Size A3	Document Number		Rev
	AG3		2
Date: Thursday, April 20, 2006		Sheet 25 of	55

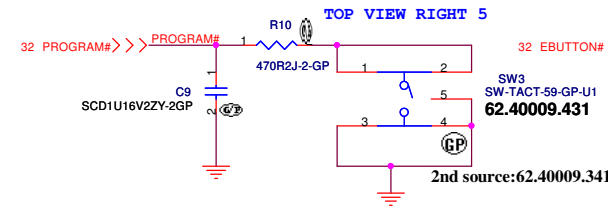
Mini Card Connector



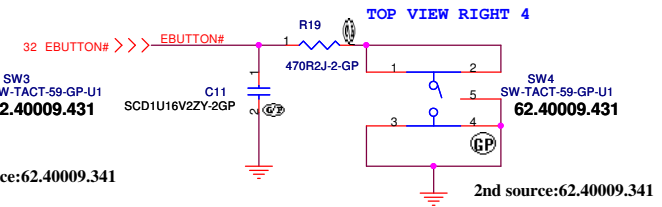
Internal Microphone



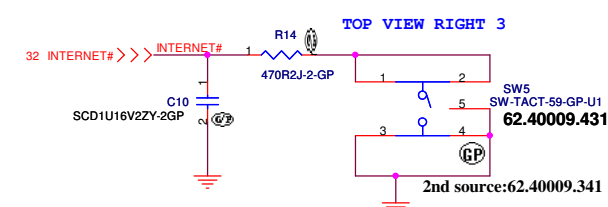
Program Button



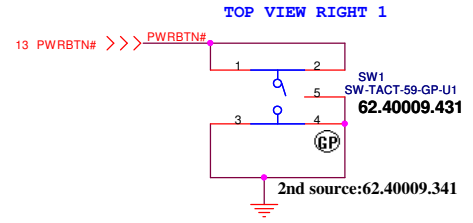
E-Button



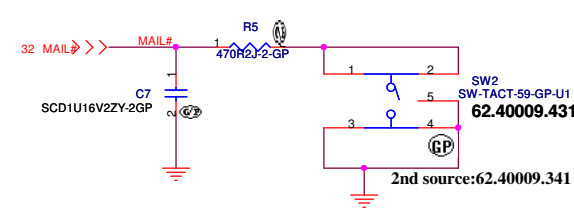
Internet Button



Power Button

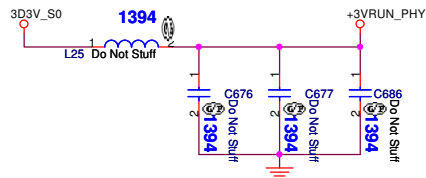
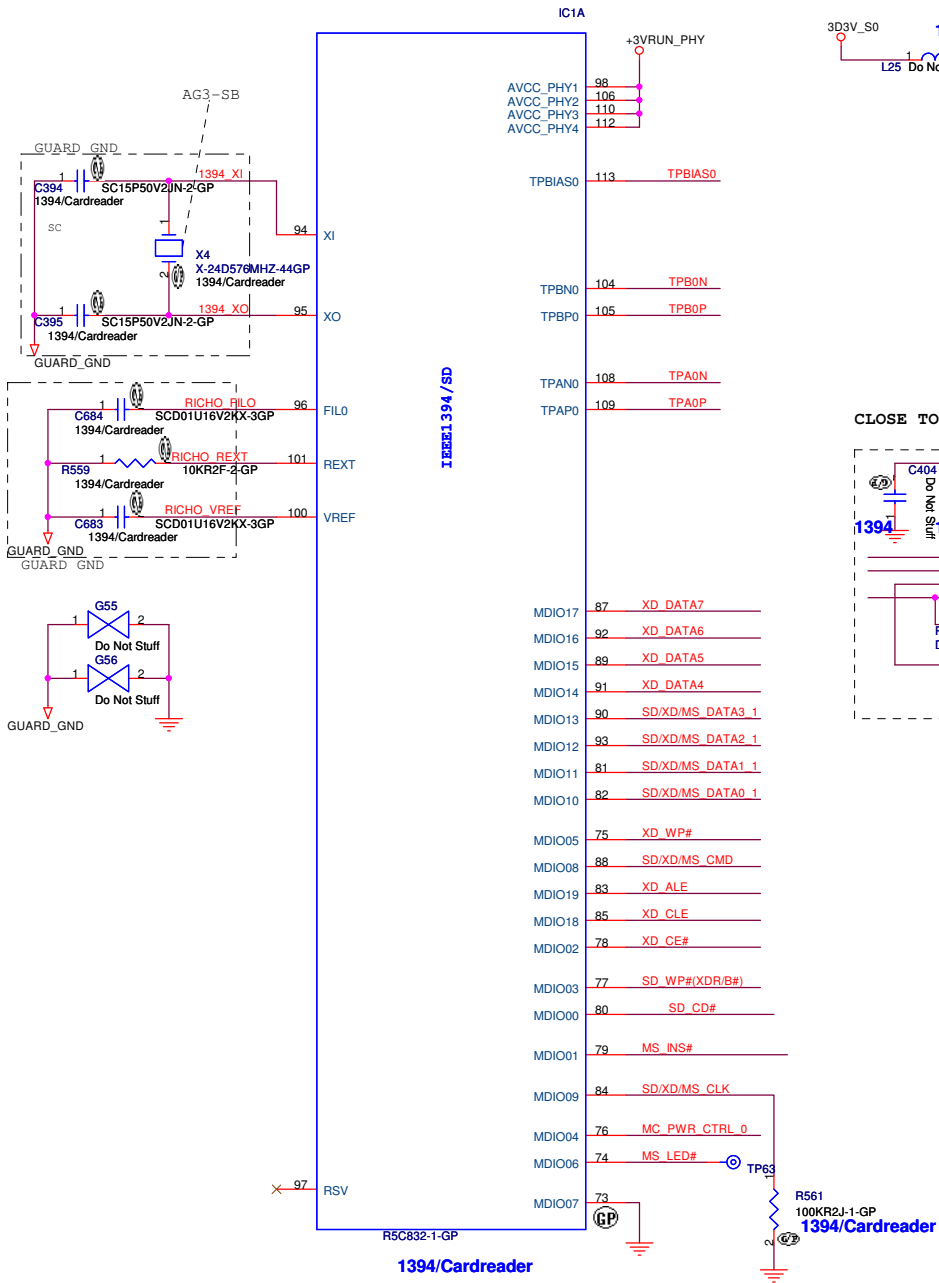


Mail Button

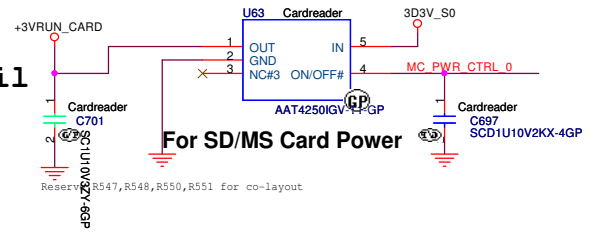


BOM		
緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
Size		
Date: Wednesday, April 26, 2006		
Sheet 26 of 55		
MINI CARD / Button AG3 2		





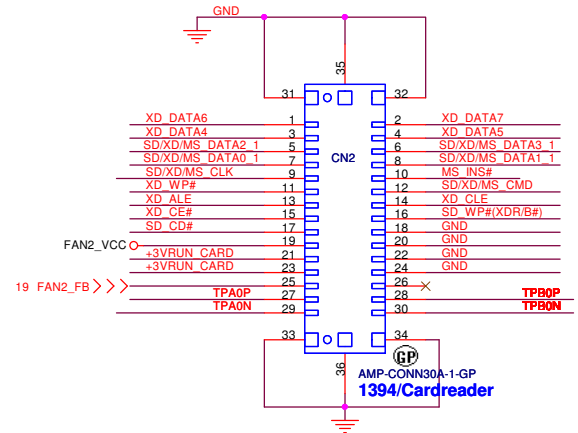
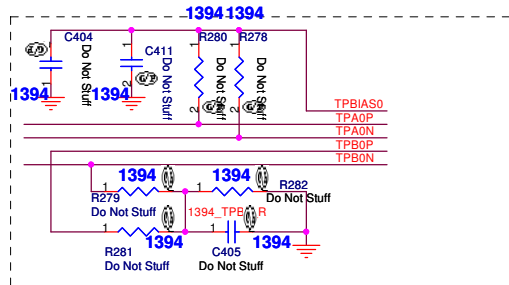
20mil



For SD/MS Card Power

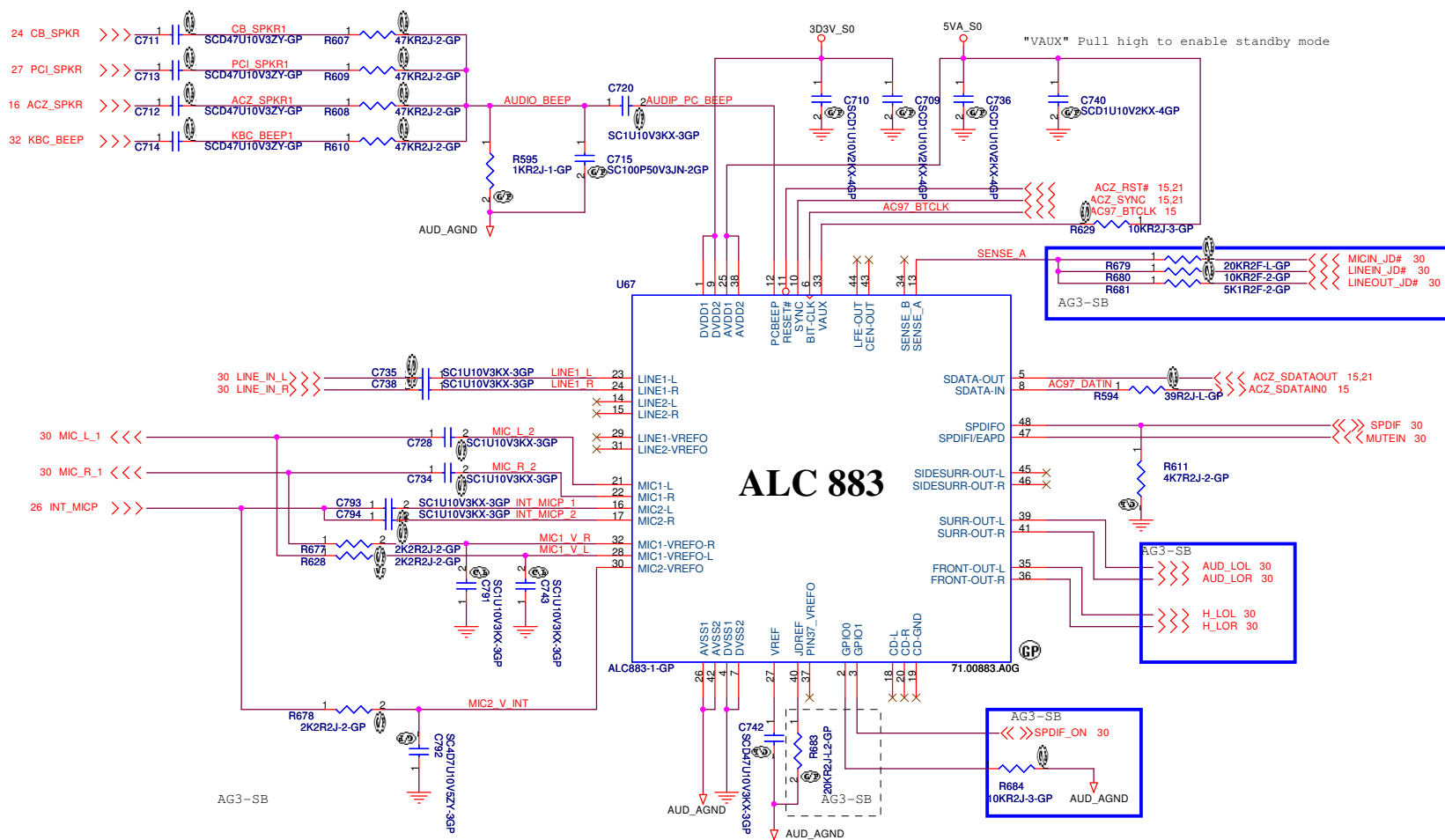
Reserve R547, R548, R550, R551 for co-layout

CLOSE TO CHIP



BOM

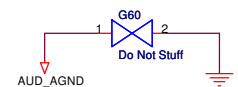
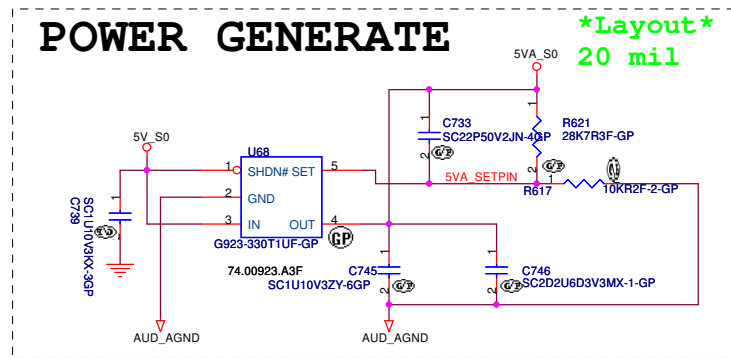
緯創資通		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
File		R5C832_1394_7IN1(2/2)	
Size A3	Document Number	AG3	
Date: Thursday, April 20, 2006	Sheet 28 of 55	Rev 2	



1) When GPIO0 is asserted, AMP should be muted.
 2) SPDIFO should be turned off when not used.

Configuration:
 (3 External Jacks, 1 internal Mic, 1 stereo output Speaker Amp.

Pin	Symbol	Location	Re-tasking
35/36	FRONT	AMP, Jack1	AMP output, line input
39/41	SURR	X	X
43/44	CEN/LEFT	X	SURR-VREFO-L/R
45/46	SIDESURR	X	SIDESURR-L is MIC2-VREFO-R, SIDESURR-R is LINE2-VREFO-R
23/24	LINE1	Jack 2	Line input, line output
21/22	MIC1	Jack 3	Mic input, line output
14/15	LINE2	X	X
16/17	MIC2	Int. Mic	Mic input

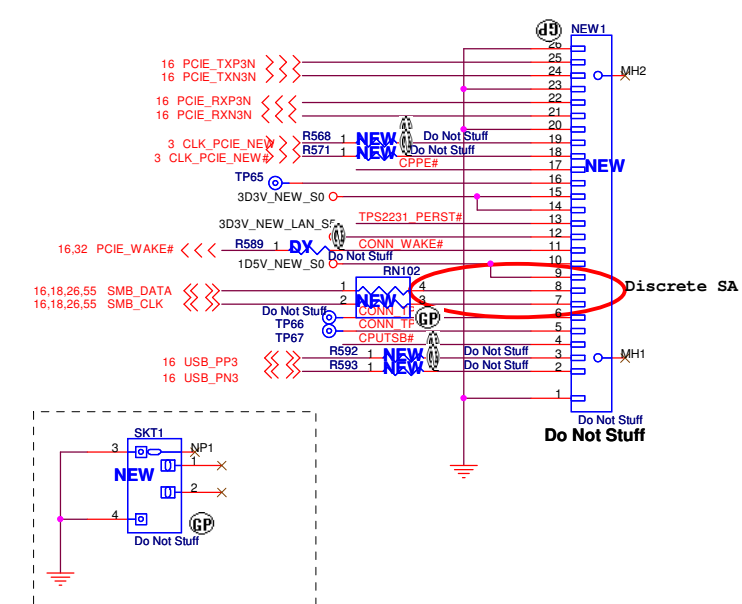
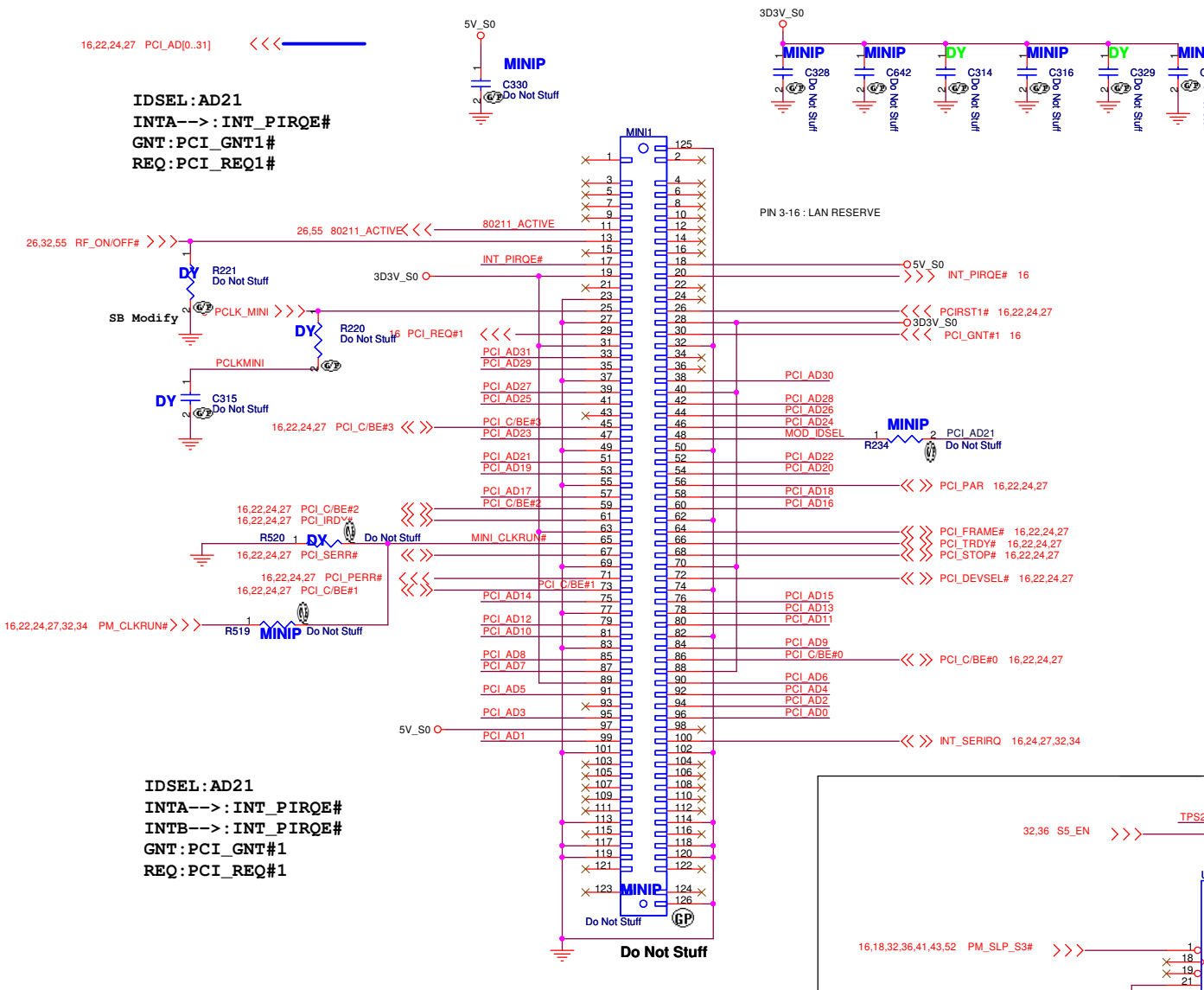


BOM

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

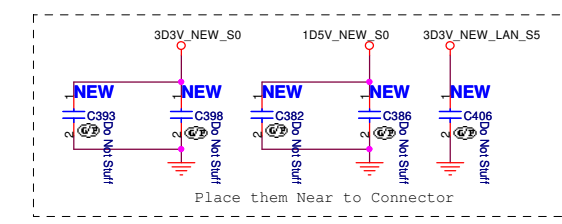
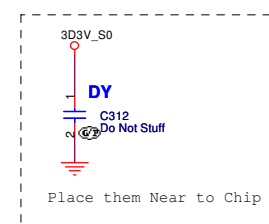
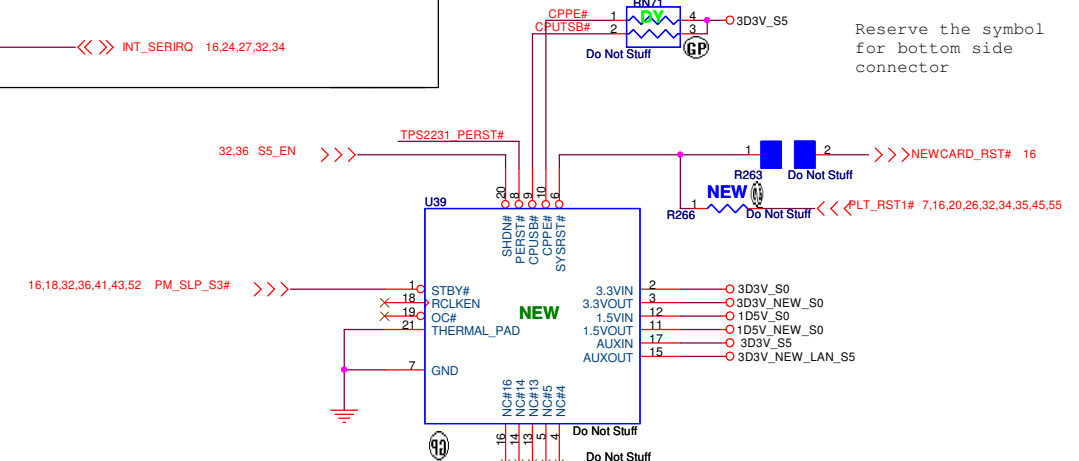
Title **Azalia codec ALC883**

Size A3	Document Number AG3	Rev 2
Date: Thursday, April 20, 2006	Sheet 29 of 55	



NEWCARD Connector

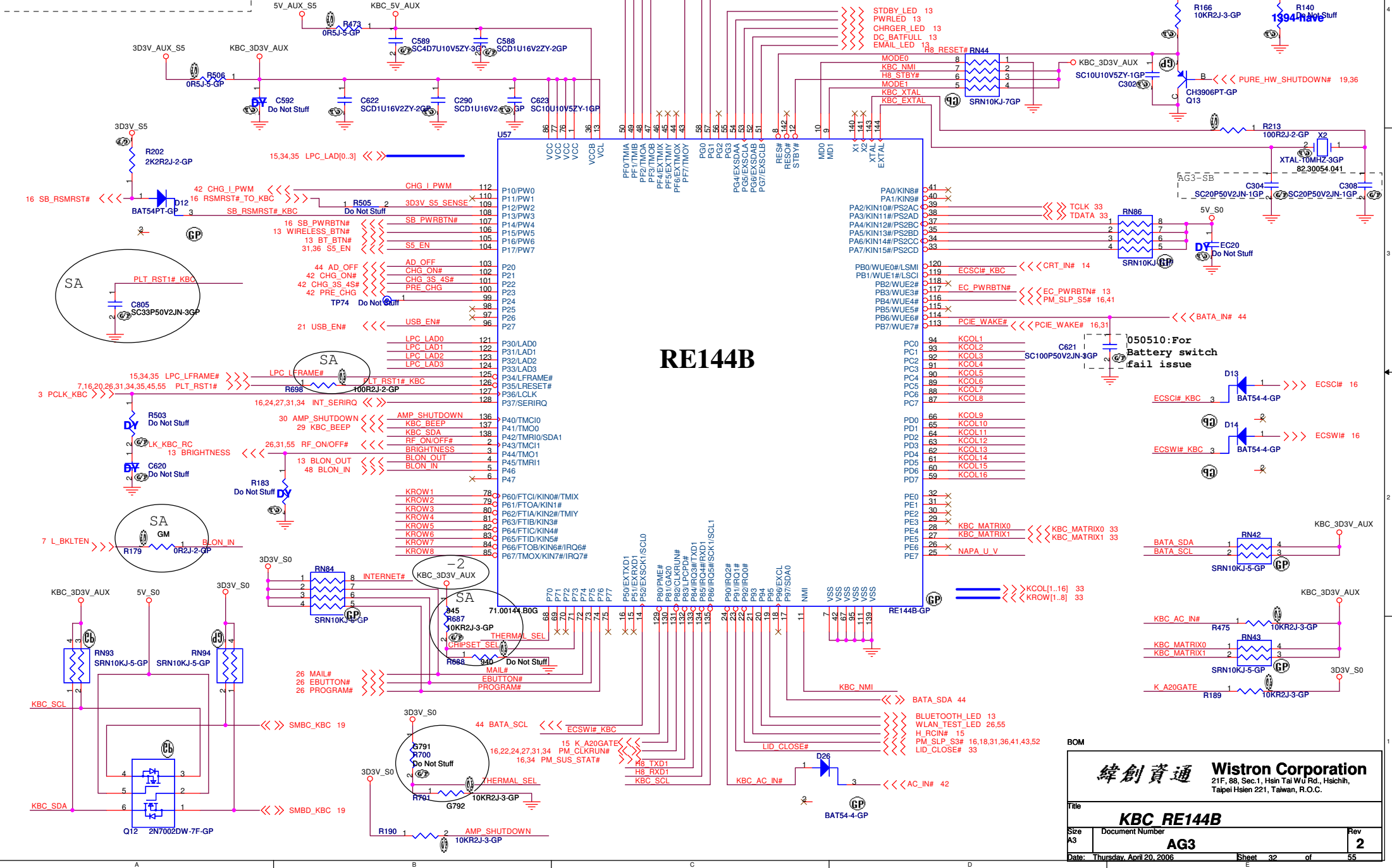
Reserve the symbol for bottom side connector



Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
File MINI-PCI/NEW Card		
Size A3	Document Number AG3	Rev 2
Date: Thursday, April 20, 2006		Sheet 31 of 55

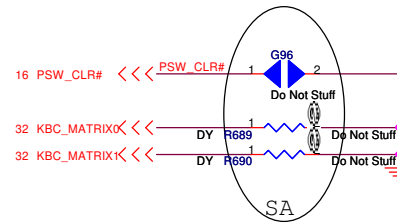
For S/W Debug

Pin No.			Pin No.
1	3D3V_AUX_KBC		2
3	H8 RESET#	TP24	MODE1
5	KBC_AC_IN#	TP48	MODE0
7	LID_CLOSE#	TP31	
9	PM_SLP_S3#	TP73	H8_TXD1
		TP29	
		TP19	H8_RXD1
		TP36	
		TP20	GND
			10



緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsein 221, Taiwan, R.O.C.

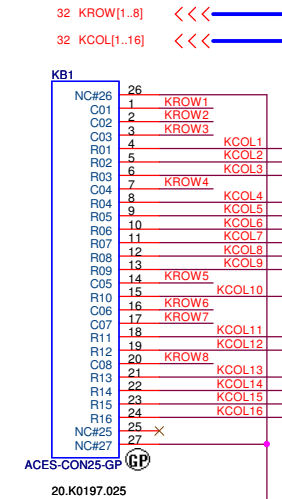
Internal KeyBoard Connector



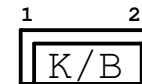
Keyboard matrix (from vendor)

	US	Eur	Jap	Ohter
MATRIXID0#	1	0	1	0
MATRIXID1#	1	1	0	0

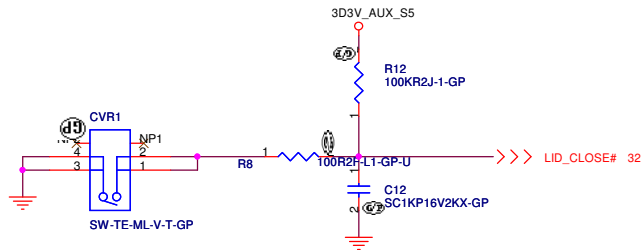
	Low Active
PSW_CLR#	1 - 5 ON
NC	2 - 6 ON
KBC_MATRIX1	3 - 7 ON
KBC_MATRIX2	4 - 8 ON



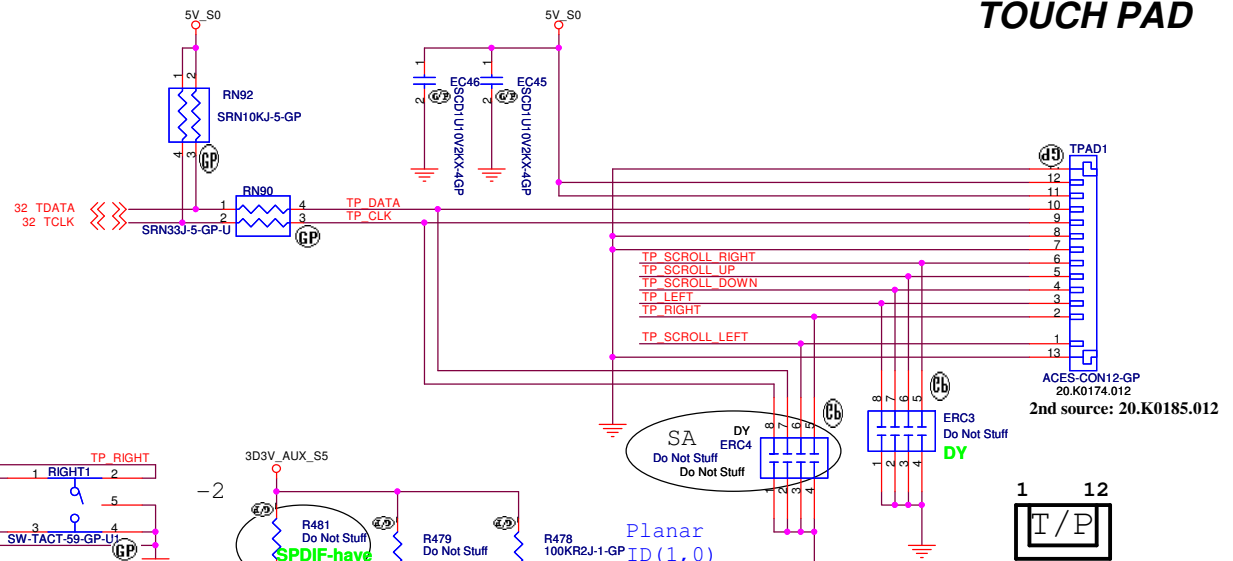
2nd source: 20.K0198.025



COVER SWITCH

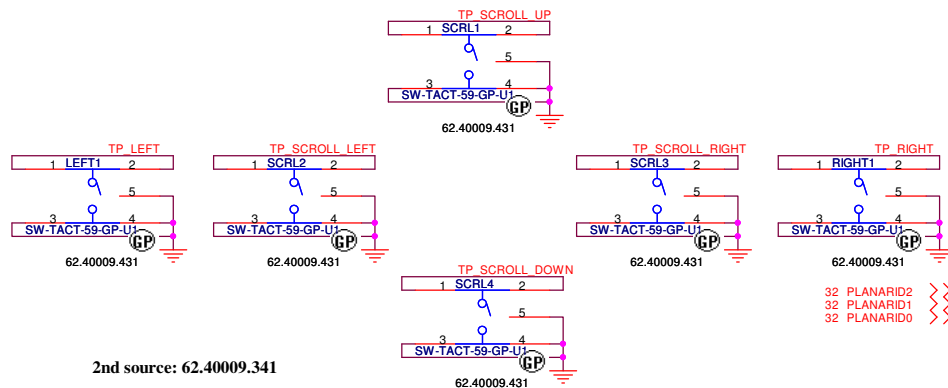


TOUCH PAD



2nd source: 20.K0185.012

SCROLL KEY



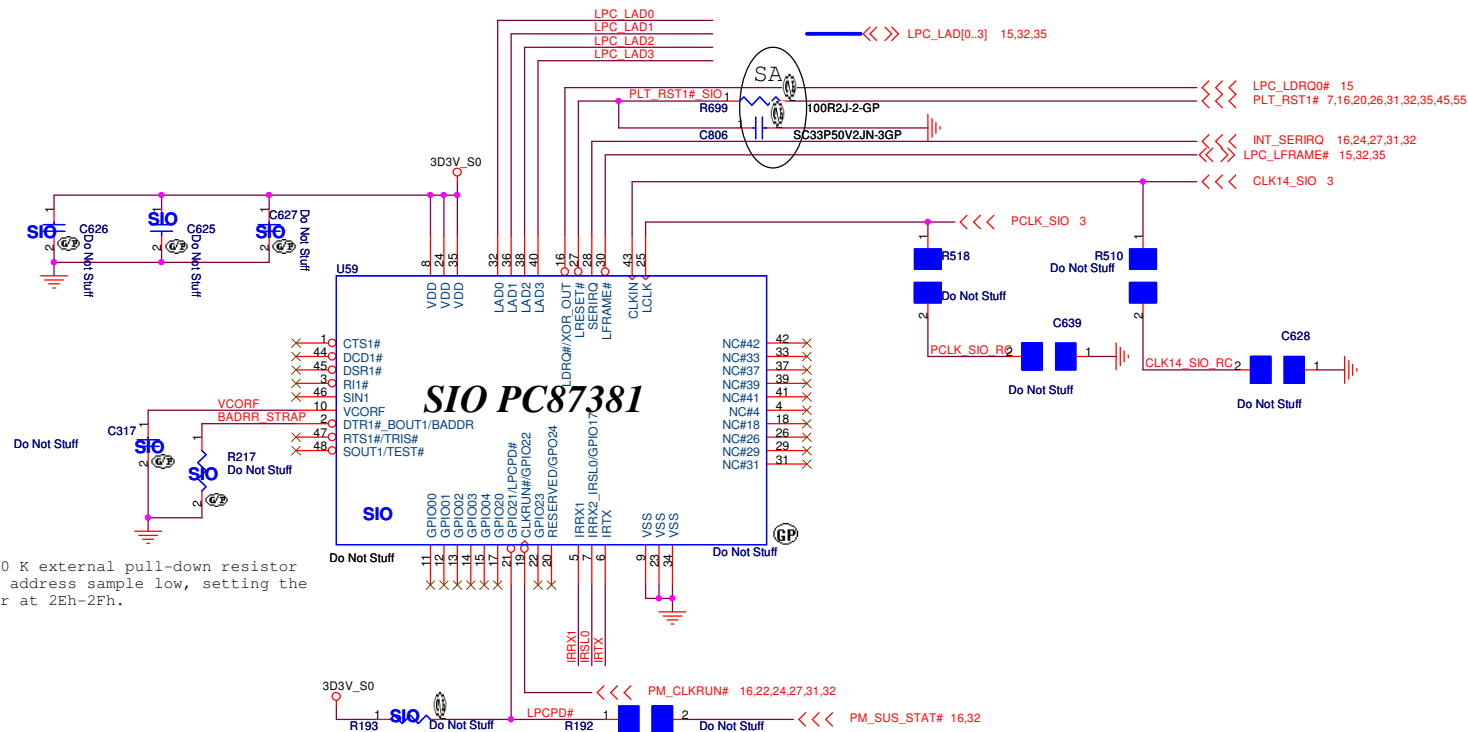
2nd source: 62.40009.341

Planar
ID(1,0)
SA: 0,0
01: 0,1
02: 1,0
03: 1,1

BOM

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

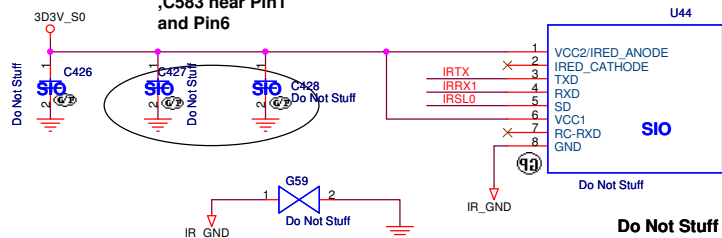
KEYBOARD/TOUCHPAD		
Size A3	Document Number AG3	Rev 2
Date: Friday, April 21, 2006	Sheet 33 of 55	



VISHAY FIR/CIR Module

Place C581
,C583 near Pin1
and Pin6

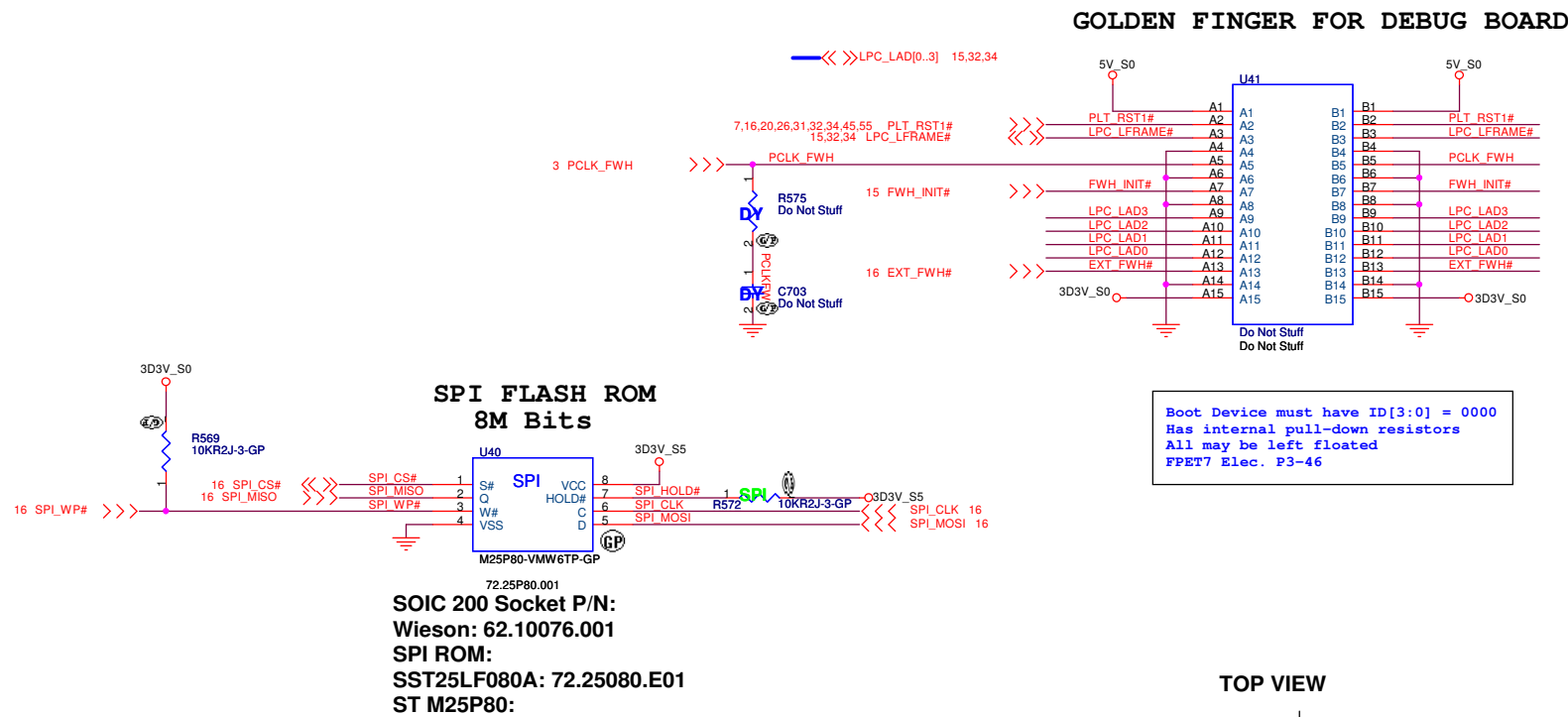
Layout Guide:
(1) FIR_3D3V : 30 mils,
(2) C583, C581 close
to U32



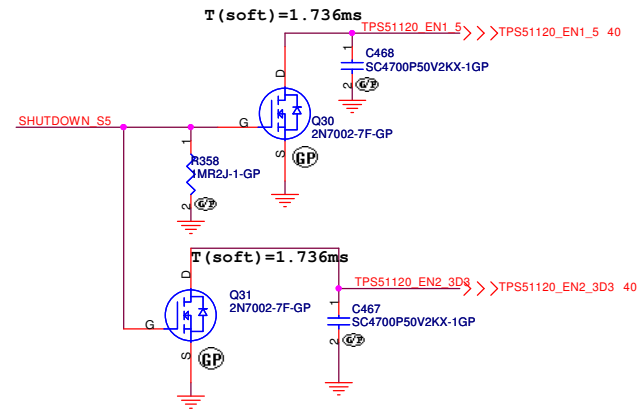
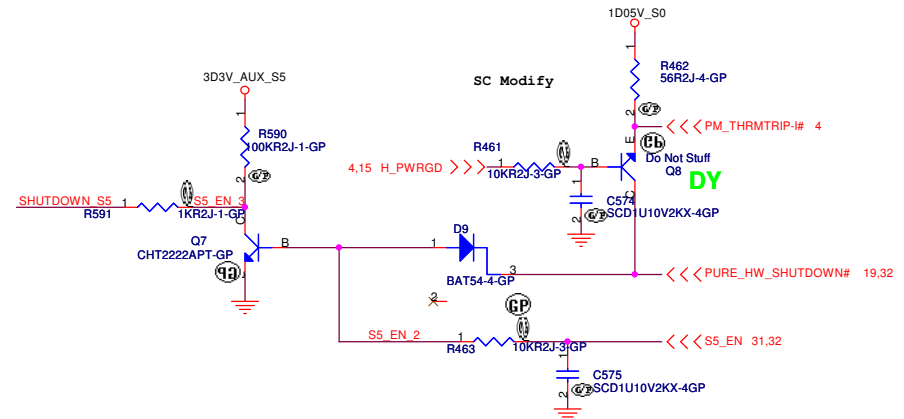
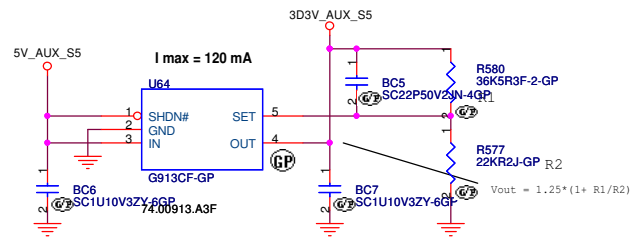
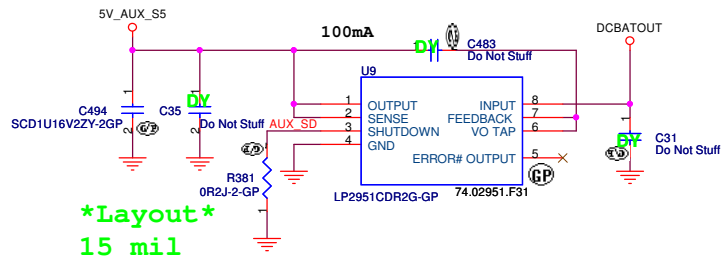
BOM

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsein 221, Taiwan, R.O.C.

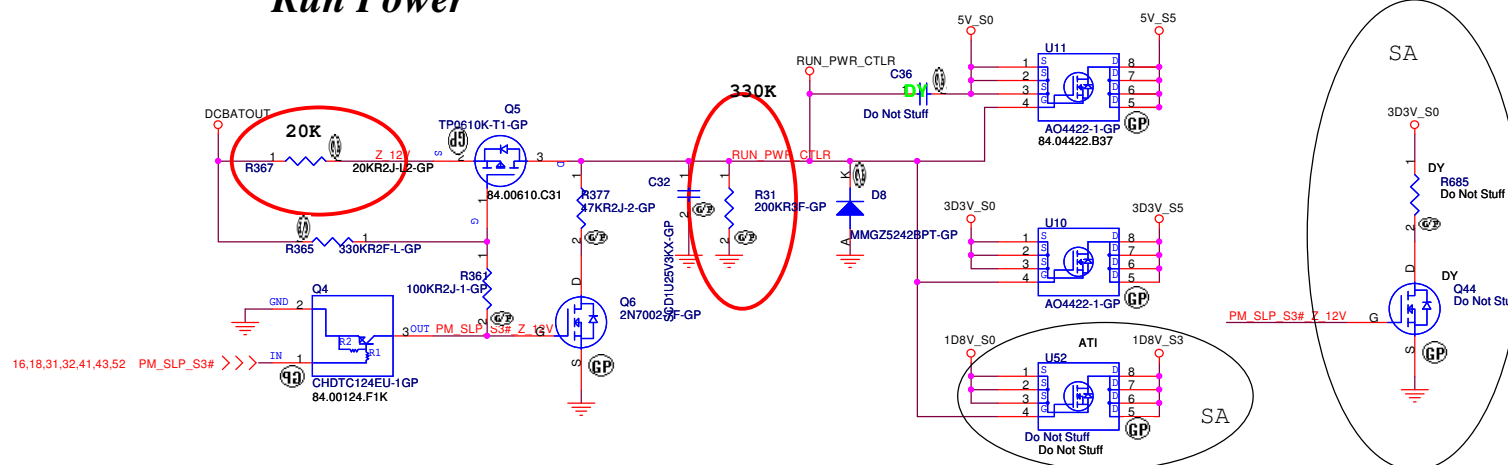
Title		
SIO 87381 / FIR		
Size	Document Number	Rev
A3	AG3	2
Date: Thursday, April 20, 2006		
Sheet 34 of 55		



Aux Power



Run Power



BOM

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
File RUN and AUX POWER	
Size A3	Document Number AG3
Date: Thursday, April 20, 2006	Sheet 36 of 55

CPU_CORE
Intersil ISL6262

H_VID0	VID0(I / 1.05V)	Output Signal PGOOD(OD / 3.3V) CLK_EN#(O)
H_VID1	VID1(I / 1.05V)	
H_VID2	VID2(I / 1.05V)	
H_VID3	VID3(I / 1.05V)	
H_VID4	VID4(I / 1.05V)	
H_VID5	VID5(I / 1.05V)	
H_VID6	VID6(I / 1.05V)	Output Power VCC_CORE_PWR(O)
PSI#	Input Signal PSI# (I / 3.3V)	
CPUCORE_ON	PGD_IN (I / 3.3V)	
PM DPRSLPVR	DPRSLPVR (I / 3.3V)	
H DPRSTP#	DPRSTP# (I / 3.3V)	
VCC_SENSE	Voltage Sense VSEN(I / Vcore)	
VSS_SENSE	RTN(I / Vcore)	
DCBATOUT_6262	Input Power VCC(I)	
5V_S0	VCC(I)	
3D3V_S0	VCC(I)	

TPS51120
5V/3D3V

	Input Signal	Output Signal
TPS51120_EN1_5	EN1	PGOOD1 (OD / 5V)
TPS51120_EN2_3D3		PGOOD2 (OD / 5V)
	EN2	Output Power
		5V (O)
		3D3V (O)
DCBATOUT_TPS51120	Input Power	
	VIN	

TI TPS51116
1.8V / 0.9V

Input Signal		Output Signal
S5 S3		PGOOD (OD / 3.3V)
Input Power		Output Power
DCBATOUT		VCC (I)
5V_S5		VCC (O)
		VCC (I)

ISL6269_1D2V

1D2V_S0_EN	Input Signal SS_STBY1 (I / 5V) FOR 1.2V	Output Power
VCC	Input Power	1D2V_PWR
DCBATOUT_6269	VIN	

CHARGER ISL6225

Input Signal		Output Signal
CHGON#/OFF		ICTL
BT_TH		PKPRES
Input Power		Output Power
AD+		ACIN
		VOUT (O)
		VOUT (O)

Adapter

Input Signal		Output Signal
AD_OFF		(I)
Input Power		Output Power
AD_JK		VCC (I)
5V_AUX_S5		VCC (I)
		VCC (O)

2D5V_S0

3D3V_S0	INPUT	OUT	2D5V_S0
---------	-------	-----	---------

APL5332KAC

1D5V_S0

1D8V_S3	INPUT	OUT	1D5V_S0
---------	-------	-----	---------

APL5912-KAC-GP

1D05V_S0

1D8V_S3	INPUT	OUT	1D05V_S0
---------	-------	-----	----------

APL5912-KAC-GP* 2

1D2V_S0

1D8V_S0	INPUT	OUT	1D2V_S0
---------	-------	-----	---------

APL5331KAC-TRL

3D3V_AUX_S5

5V_S5_G913	INPUT	OUT	3D3V_AUX_S5
------------	-------	-----	-------------

G913CF

5V_AUX_S5

DCBATOUT	INPUT	OUT	5V_AUX_2591
----------	-------	-----	-------------

LP2951ACM

BOM

緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Power Block Diagram	
Size A3	Document Number AG3
Date: Thursday, April 20, 2006	Sheet 37 of 55

Place close to phase 1 choke
If NTC=330Kohm, R10=8.66K

5 H_VID[0..6]

40,41,43,48 CPUCORE_ON

16 PM DPRSLPVR

4,15 H DPRSLP#

3 CLK_EN#

Switching Frequency=300KHz

When test without cpu,
R183 & R184 change to 0 ohms
If VCC_SENSE and VSS_SENSE pins have pulled
resistors to VCC_CORE_S0
==> Remove R183/R184

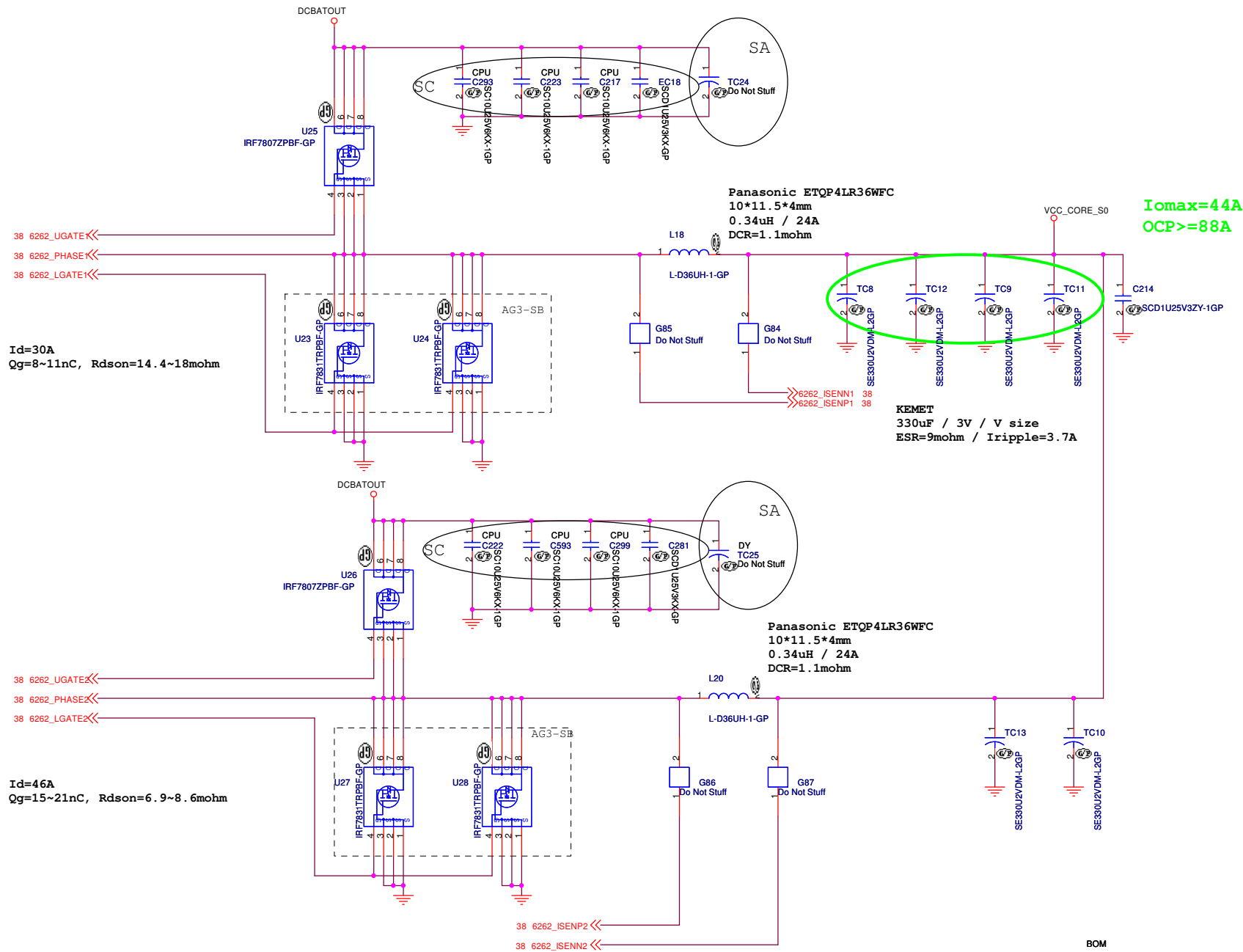
PGOOD
Power good open-drain output.
Will be pulled up externally by
a 680. resistor to VCCP or 1.9k. to 3.3V.

Place close to phase 1 choke

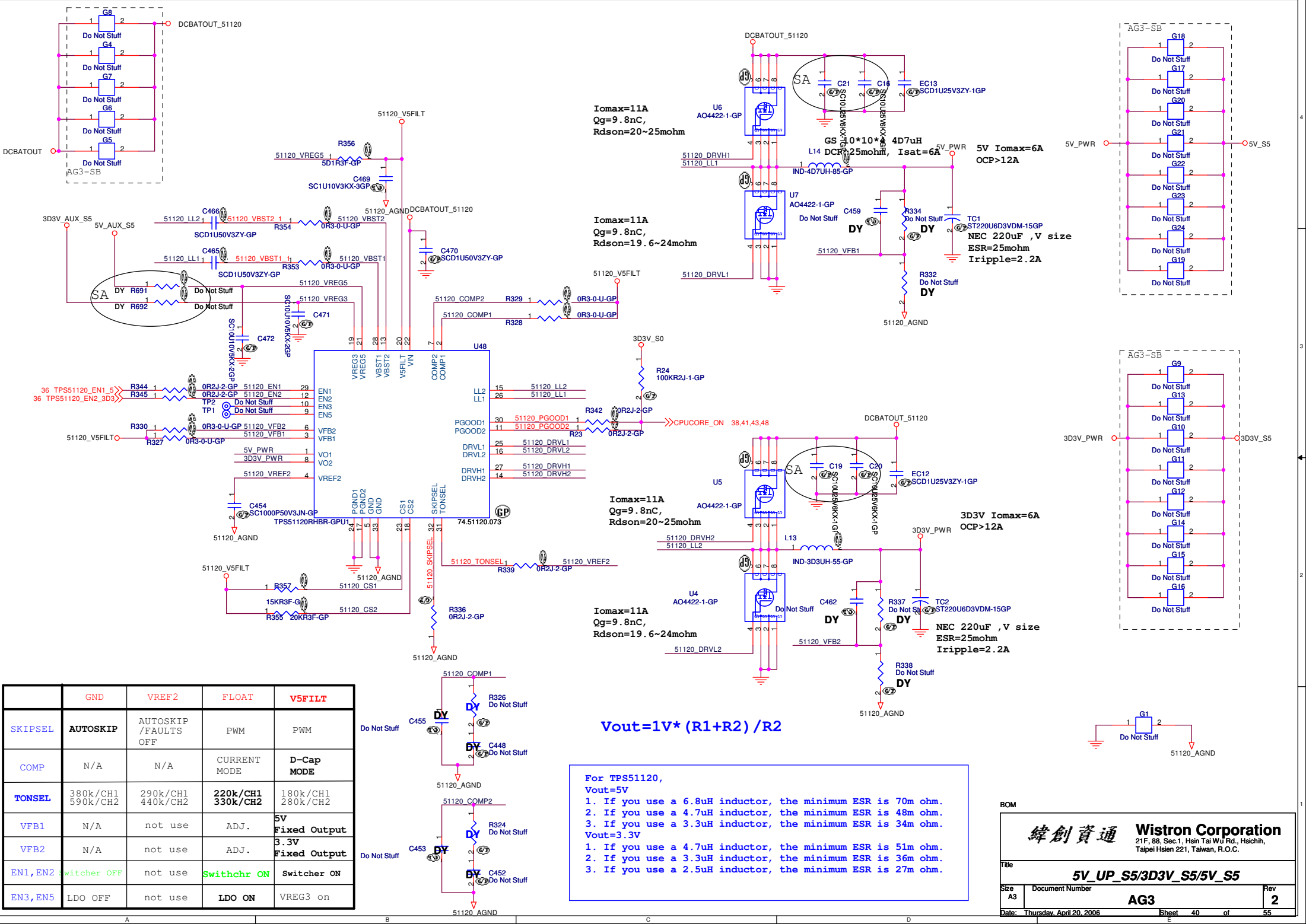
Load Line

OCP>=50A

BOM	
緯創資通 Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title	
CPU Vcore Power_1	
Size A3	Document Number
AG3	
Date: Thursday, April 20, 2006	Sheet 38 of 55
Rev 2	



BOM



	GND	VREF2	FLOAT	V5FILT
SKIPSEL	AUTOSKIP	AUTOSKIP /FAULTS OFF	PWM	PWM
COMP	N/A	N/A	CURRENT MODE	D-Cap MODE
TONSEL	380k/CH1 590k/CH2	290k/CH1 440k/CH2	220k/CH1 330k/CH2	180k/CH1 280k/CH2
VFB1	N/A	not use	ADJ.	5V Fixed Output
VFB2	N/A	not use	ADJ.	3.3V Fixed Output
EN1,EN2	Switcher OFF	not use	Switcher ON	Switcher ON
EN3,EN5	LDO OFF	not use	LDO ON	VREG3 on

For TPS51120,
Vout=5V

1. If you use a 6.8uH inductor, the minimum ESR is 70m ohm.
2. If you use a 4.7uH inductor, the minimum ESR is 48m ohm.
3. If you use a 3.3uH inductor, the minimum ESR is 34m ohm.

Vout=3.3V

1. If you use a 4.7uH inductor, the minimum ESR is 51m ohm.
2. If you use a 3.3uH inductor, the minimum ESR is 36m ohm.
3. If you use a 2.5uH inductor, the minimum ESR is 27m ohm.

BOM

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

5V_UP_S5/3D3V_S5/5V_S5

Size A3

Document Number

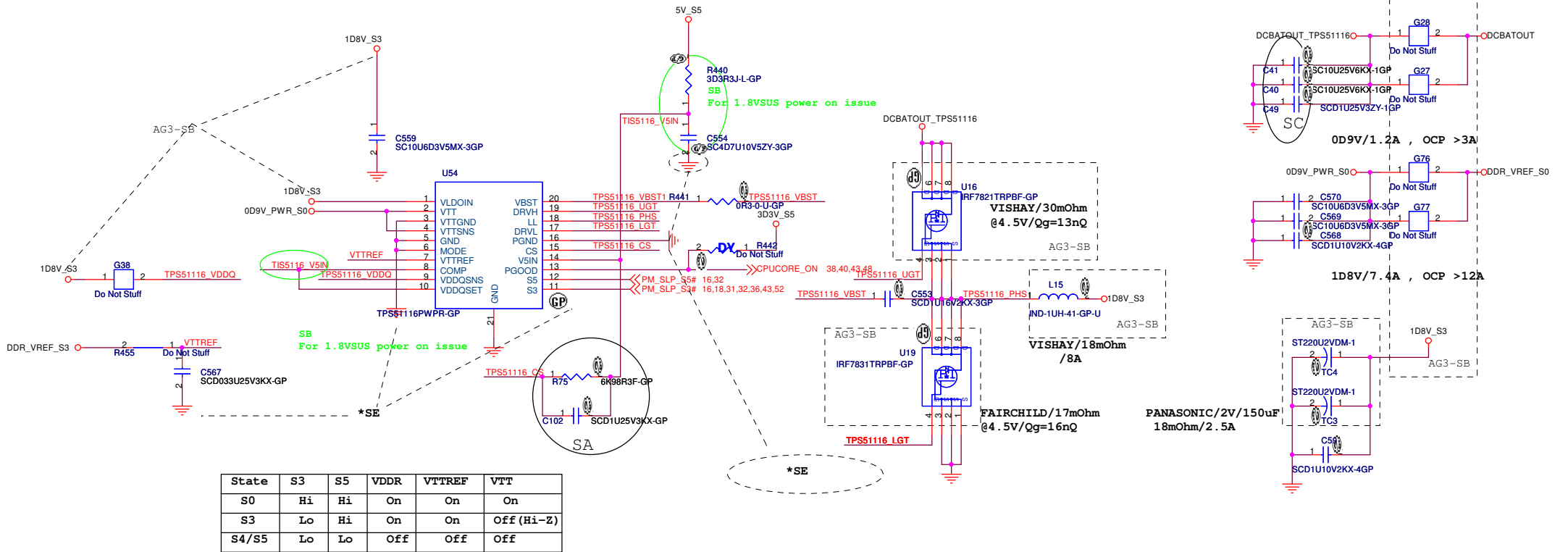
AG3

Date: Thursday, April 20, 2006

Sheet 40 of 55

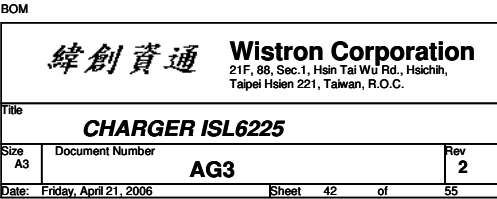
Rev 2

TI TPS51116 for 1D8V and 0D9V

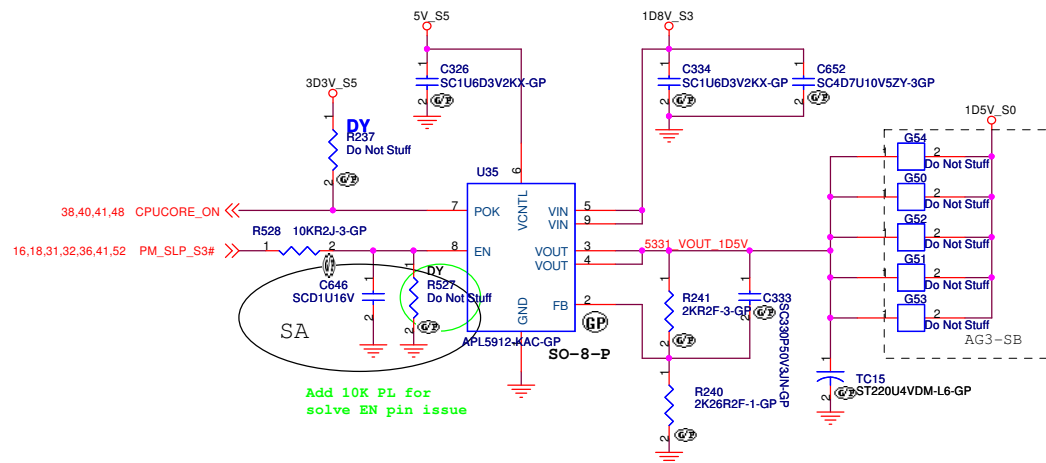
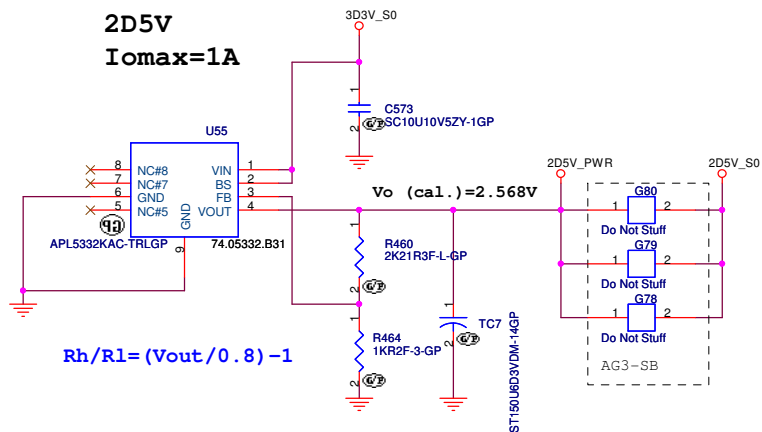


BOM

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
DC to DC 1.8V & 0.9V	
Title Size A3 Date: Friday, April 21, 2006	Document Number AG3 Sheet 41 of 55
Rev 2	Rev 2



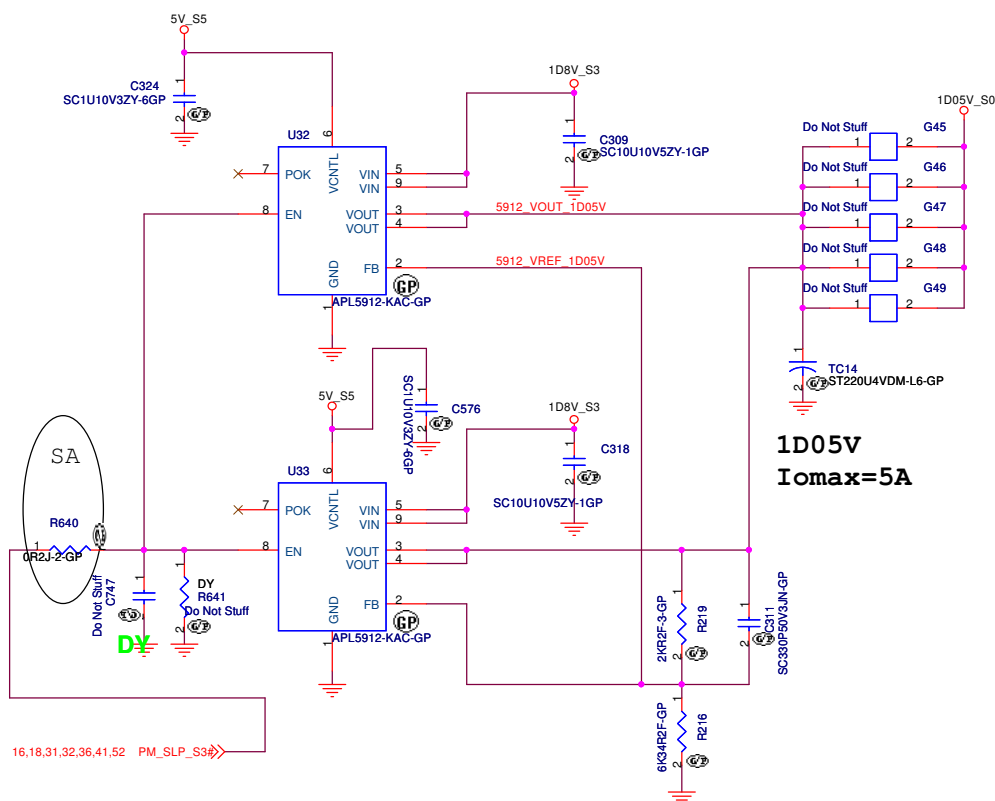
2D5V
Iomax=1A



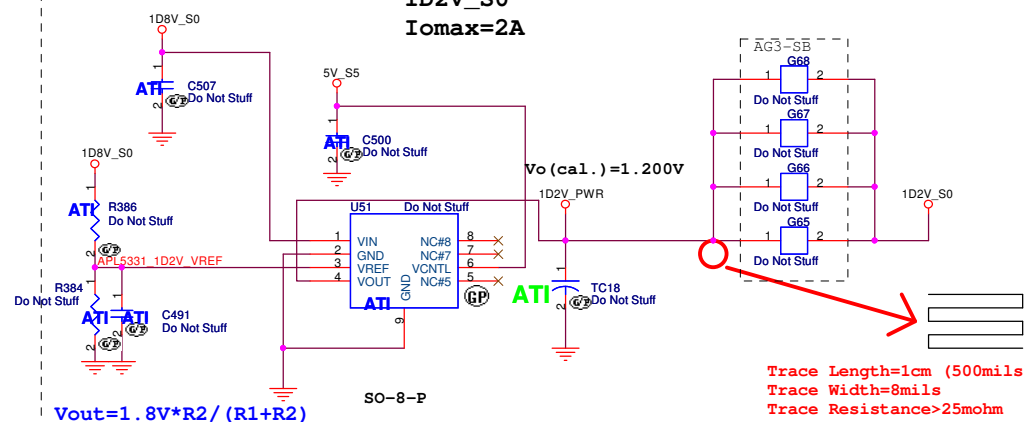
KEMET
100uF, 6V, B2 Size
ESR=40mohm

$$Vo = 0.8 * (1 + (R1/R2))$$

AG3-SB



1D2V_S0
Iomax=2A



BOM

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
1D2V/1D5V/2D5V/1D05V_S0		
Size	Document Number	Rev
A3	AG3	2
Date:	Thursday, April 20, 2006	Sheet 43 of 55

AG3-SB

DSC : 22.10037.C61
UMA : 22.10037.C51

945-940

DCIN1

4

1

2

3

5

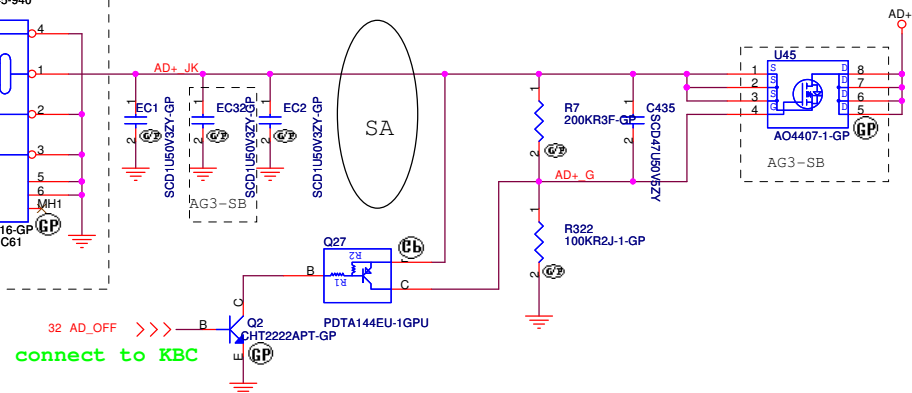
6

MH1

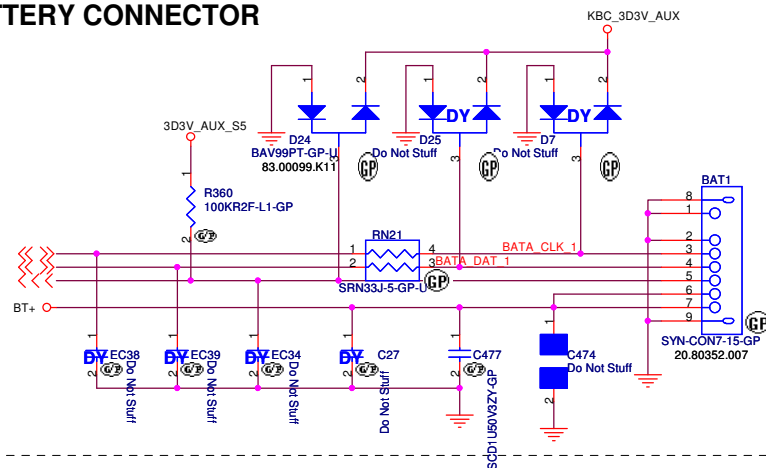
DC-JACK116-GP
22.10037.C61

GP

Ground



```
32 BATA_SCL
32 BATA_SDA
32 BATA_IN#
```



緯創資通

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

AD/BATT CONN

Document Number

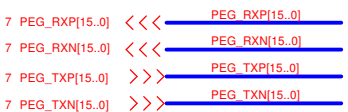
AG3

Rev	2
-----	---

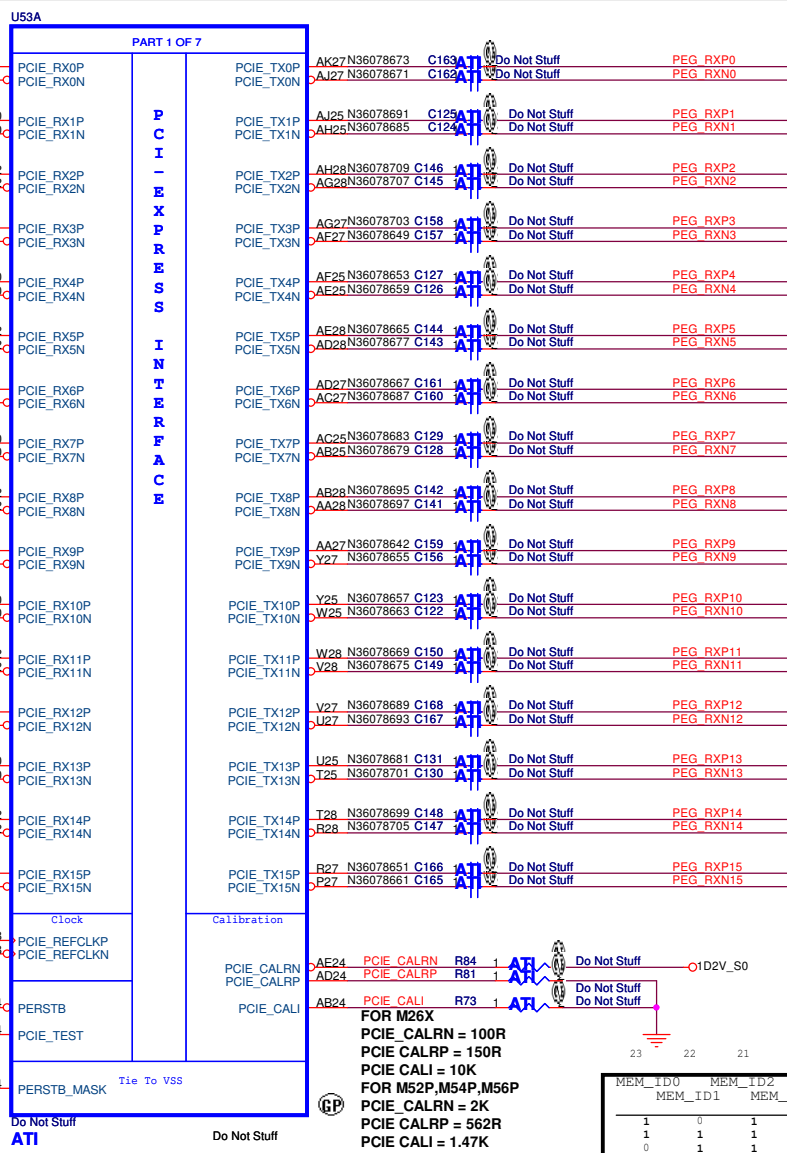
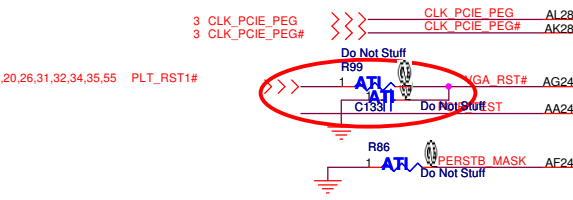
Date: Friday, April 21, 2006

Sheet 44 of 55

PCIE TEST PADS
PCIE TEST POINTS MUST BE WITHIN 250 MILS
OF THE ASIC BALL WITH POSITIVE AND NEGATIVE
SIGNALS THE SAME DISTANCE

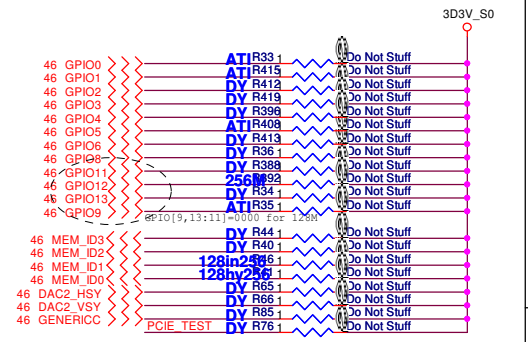


PCIE SIGNALS CONNECT TO ROOT COMPLEX
REFER TO PCI EXPRESS DESIGN GUIDE
FOR RECOMMENDED AC COUPLING CAPS
PLACEMENT ALONG THE TX INTERCONNECT



M56: 71.0M56P.M01
M54: 71.0M54P.B0U
M52: 71.0M52P.B0U

STRAPS	PIN	DESCRIPTION OF RECOMMENDED SETTING	RECOMMENDED
STRAP_B_PTX_PWRS_ENB	GPIO0	TRANSMITTER POWER SAVINGS ENABLE - FULL TX OUTPUT SWING	INSTALL 10K RESISTOR
STRAP_B_PTX_DEEMPH_EN	GPIO1	TRANSMITTER DE-EMPHASIS ENABLE DEPENDS ON PCIE CHIPSET BEING USED FOR M26X,M5X INSTALL WITH ATI RS480,RS400,RX480, RC410,RS482 CHIPSETS FOR M26X ONLY DO NOT INSTALL WITH INTEL 915PM CHIPSET	TBD
RSVD	GPIO(3:2)	NO ATI FEATURE ENABLED	DO NOT INSTALL 10K RESISTORS
REVERSE LANES DEBUG ACCESS	GPIO4	NOT REVERSED LANE (M26X) NO DEBUG ACCESS (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTOR
STRAP_FORCE_COMPLIANCE sets the desired PCIE PLL bandwidth for M5x parts.	GPIO5	DO NOT FORCE COMPLIANCE STATE QUICKLY (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	INSTALL 10K RESISTORS
COMMON MODE RANGE RSVD	GPIO6	NORMAL RANGE (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
DEBUG ACCESS FORCE_COMPLIANCE	GPIO8	NO DEBUG ACCESS (M26X) DON'T FORCE COMPLIANCE STATE(M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
ROMIDCFG(3:0)	GPIO[9,13:11]	SERIAL FLASH ROM TYPE (M26X,M52P,M54P,M56P) - SERIAL M25P10 ROM	1011
MEMORY APERTURE SIZE	GPIO[13:11]	IF NO ROM GPIO11(M26X) AND GPIO12,13(M52,M54,M56) SET MEMORY APERTURE SIZE SEE M26X,M54X,M56X DATA BOOK FOR MEMORY,FRAME BUFFER APERTURE SETTINGS	TBD
MEM_TYPE	MEMID (3:0)	MEMORY TYPE AND SPEED SELECT	TBD
RSVD NO STRAP FUNCTION	H2SYNC V2SYNC GENERICCC	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	DO NOT INSTALL 10K RESISTORS
RSVD NO STRAP FUNCTION	PCIE_TEST	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	



MEM_ID0	MEM_ID1	MEM_ID2	MEM_ID3	MEM	SIZE	VENDOR	CHIPS
1	0	1	0	64M	16M*16	Infineon	x2
1	1	1	0	64M	16M*16	Hynix	x2
0	1	1	0	128M	16M*16	Samsung	x4
0	0	1	0	256M	32M*16	Infineon	x4
0	1	0	0	128M	16M*16	Infineon	x4
1	1	0	0	128M	16M*16	Hynix	x4
0	0	0	0	256M	32M*16	Hynix	x4

When no ROM is attached, GPIO[9] is set to 0.
GPIO[13:12] is used to select the frame buffer aperture size.
GPIO[13:12] = 00: 128M frame buffer, same as ROM strap 00
GPIO[13:12] = 01: 256M frame buffer, same as ROM strap 01
GPIO[13:12] = 10: 64M frame buffer, same as ROM strap 10
GPIO[13:12] = 11: reserved, same as ROM strap 11

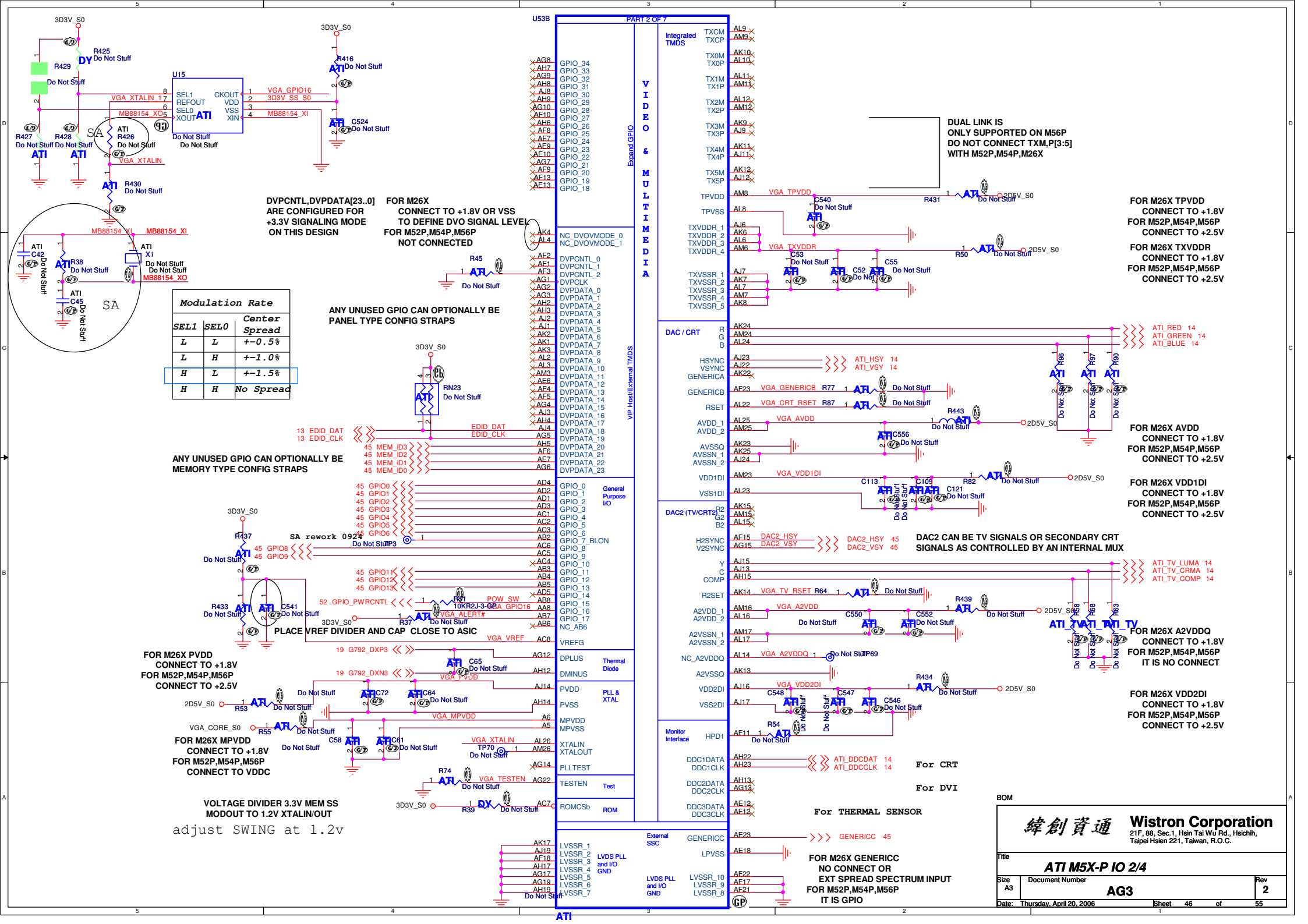
BOM

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,
Taipai Hsien 221, Taiwan, R.O.C.

Title: **ATI M5X-P PCIE 1/4**

Size A3 Document Number **AG3** Rev 2

Date: Thursday, April 20, 2006 Sheet 45 of 55



Modulation Rate		
SEL1	SEL0	Center Spread
L	L	+0.5%
L	H	+1.0%
H	L	+1.5%
H	H	No Spread

ANY UNUSED GPIO CAN OPTIONALLY BE MEMORY TYPE CONFIG STRAPS

FOR M26X PVDD
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

FOR M26X MPVDD
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO VDDC

VOLTAGE DIVIDER 3.3V MEM SS
MODOUT TO 1.2V XTALIN/OUT
adjust SWING at 1.2v

ANY UNUSED GPIO CAN OPTIONALLY BE PANEL TYPE CONFIG STRAPS

DVPCNTL,DVpdata[23..0]
ARE CONFIGURED FOR
+3.3V SIGNALING MODE
ON THIS DESIGN

FOR M26X
CONNECT TO +1.8V OR VSS
TO DEFINE DVO SIGNAL LEVEL
FOR M52P,M54P,M56P
NOT CONNECTED

VIDEO & MULTIMEDIA

VIP Host/External TMD5

General Purpose I/O

Thermal Diode

PLL & XTAL

Test

ROM

LVDS PLL and I/O GND

LVDS PLL and I/O GND

ATI

DUAL LINK IS
ONLY SUPPORTED ON M56P
DO NOT CONNECT TXM,P[3:5]
WITH M52P,M54P,M26X

FOR M26X TPVDD
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

FOR M26X TXVDDR
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

FOR M26X AVDD
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

FOR M26X VDD1DI
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

FOR M26X A2VDDQ
CONNECT TO +1.8V
FOR M52P,M54P,M56P
IT IS NO CONNECT

FOR M26X VDD2DI
CONNECT TO +1.8V
FOR M52P,M54P,M56P
CONNECT TO +2.5V

For THERMAL SENSOR

FOR M26X GENERICC
NO CONNECT OR
EXT SPREAD SPECTRUM INPUT
FOR M52P,M54P,M56P
IT IS GPIO

BOM

緯創資通

Wistron Corporation

21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title

ATI M5X-P IO 2/4

Size

A3

Document Number

AG3

Rev

2

Date

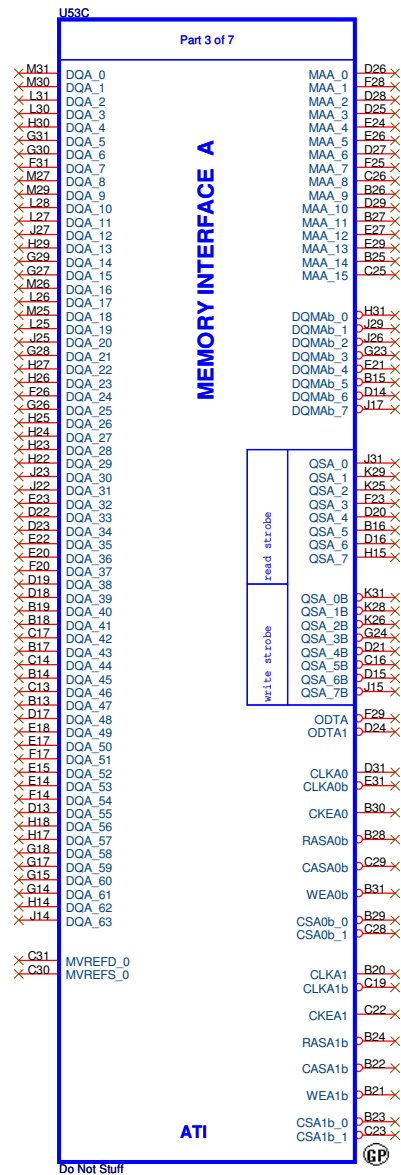
Thursday, April 20, 2006

Sheet

46

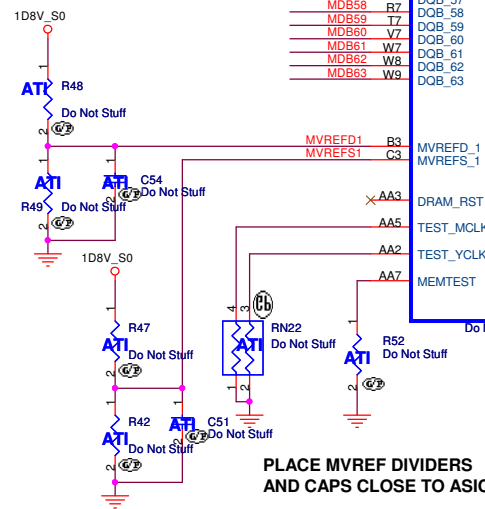
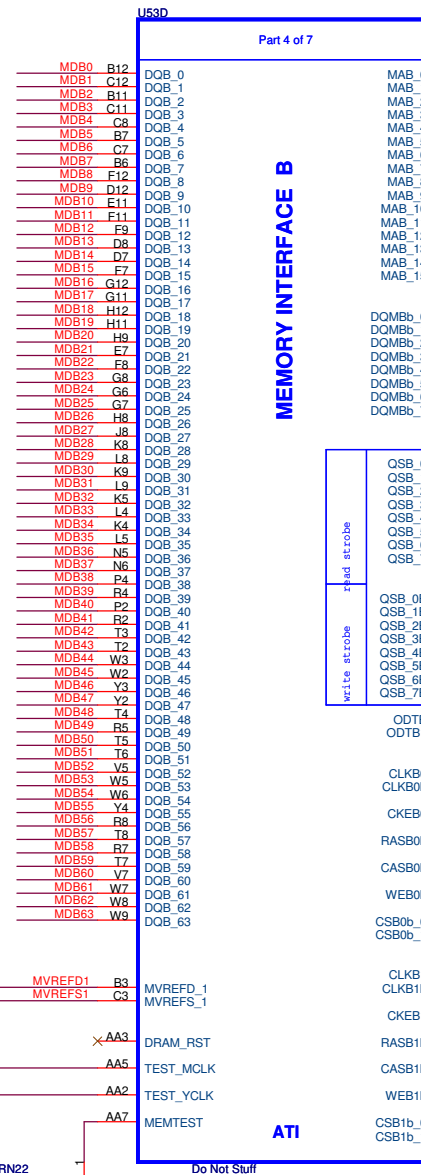
of

55

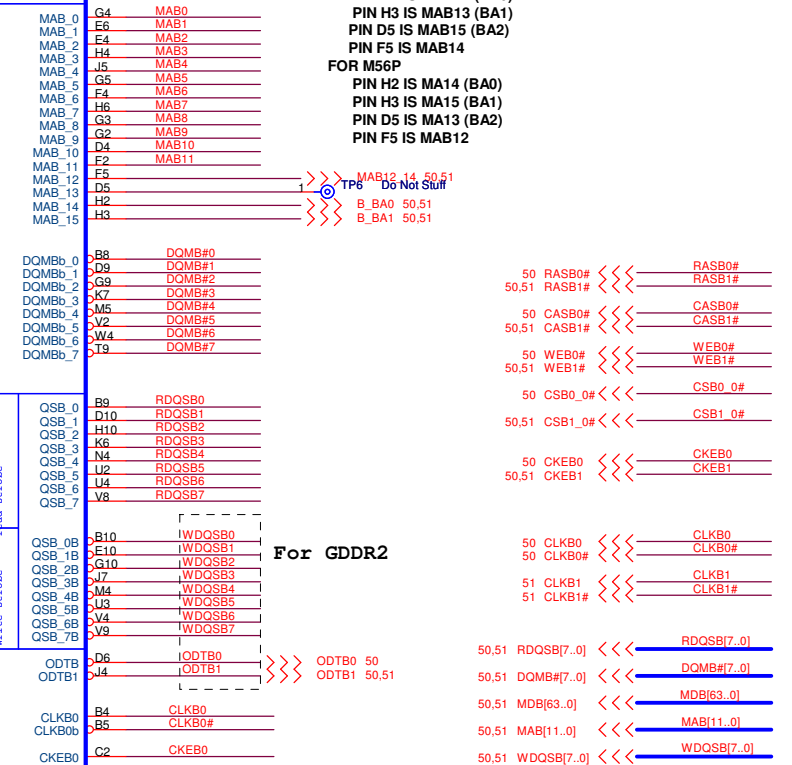


PLACE MVREF DIVIDERS
AND CAPS CLOSE TO ASIC

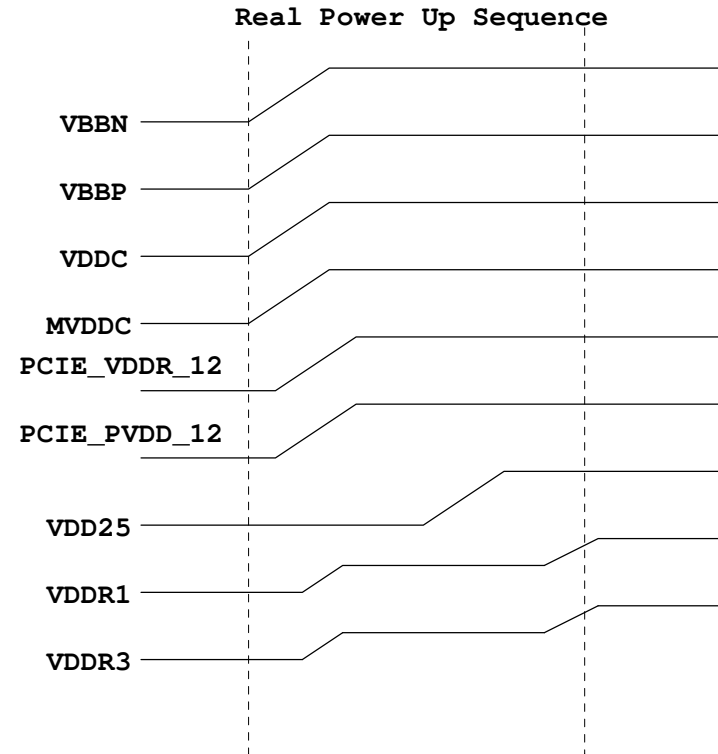
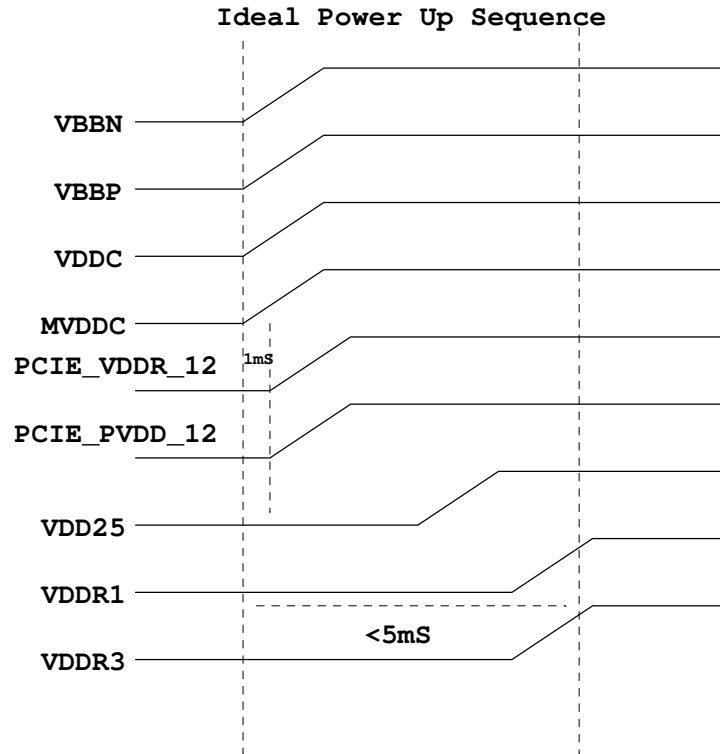
Ch-A
FOR M52P,M54P,M26X
PIN B25 IS MA12 (BA0)
PIN C25 IS MA13 (BA1)
PIN E29 IS MA15 (BA2)
PIN E27 IS MA14
FOR M56P
PIN B25 IS MA14 (BA0)
PIN C25 IS MA15 (BA1)
PIN E29 IS MA13 (BA2)
PIN E27 IS MA12



Ch-B
FOR M52P,M54P,M26X
PIN H2 IS MAB12 (BA0)
PIN H3 IS MAB13 (BA1)
PIN D5 IS MAB15 (BA2)
PIN F5 IS MAB14
FOR M56P
PIN H2 IS MA14 (BA0)
PIN H3 IS MA15 (BA1)
PIN D5 IS MA13 (BA2)
PIN F5 IS MAB12



BOM



RESISTOR

Symbol name	Value	Tolerance (J: 5%, F: 1%, D: 0.5%, B: 0.1 %)	Rating 0402=> 1/16W, 25V 0603 => 1/16W, 75V 0805 => 1/10W, 100V	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
10KR3	10K Ohm	If no letter, it means J: 5%	1/16W, 75V	0603
33D3R5	33.3 Ohm	If no letter, it means J: 5%	1/10W, 100V	0805
1KR3F	1K Ohm	F: 1%	1/16W, 75V	0603

The naming rule is value + R + size + tolerance
For the value, it can be read by the number before R. (R means resistor)
For the tolerance, it can be read from the last letter.
For the rating, we don't show on the symbol name.
For the size, R2=>0402, R3=>0603, R5=>0805,.....

General Guidelines:

- BBN and BBP must ramp up before or at the same time as VDDC but not after.
- VDDC and MVDDC must be ramped up first, followed by PCIE_VDDR_12, PCIE_PVDD12, VDD25, VDDR1 and VDDR3 (and other I/O powers).
- All powers must be ramped up within 5ms of each other (from the ramp of VDDC to 90% of VDDR3).
- VDD25 can be ramped with VDDC or VDDR1 but it cannot be ramped later than VDDR1.
- The power down is the opposite of the power on sequence: VDDR3/VDDR1 -> VDD25 ->VDDC/MVDDC/BBN/BBP.

Due to the level shifter design in the memory I/Os, in order to avoid over-stressing the thin oxide transistors when VDDR1 is powered on but VDDC is not, VDDC must ramp up before VDDR1. Similarly, VDDC must ramp up before VDDR3. The level shifter design is a function of the transistor types used in 90nm technology and of the voltage level support. The drawback of ramping up VDDC before the I/O voltages (such as VDDR1 and VDDR3) is that parasitic P/N junctions are forward biased, thus creating a conduction path. These conduction paths will pump up VDDR1 (from the memory I/Os) and VDDR3 (from the GPIOs).

The real power up sequence will appear as follows:

Figure 2-2. Real Power Up Sequence

As long as MVDDC ramps up with VDDC, the pump voltage on VDDR1 should be all right since the DRAM spec will not be violated.

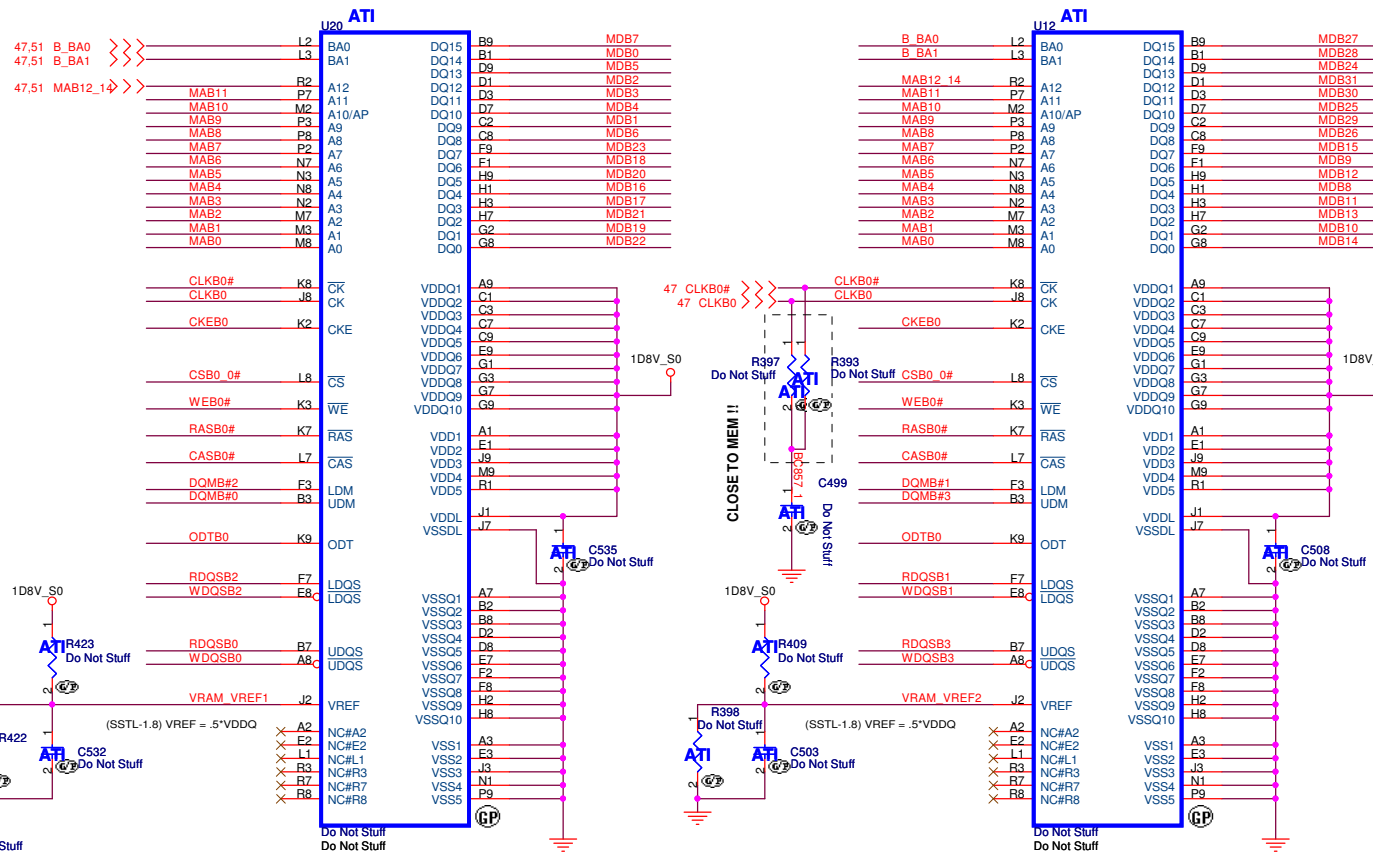
CAPACITOR

Symbol name	Value	Tolerance (J: +/-5, K: +/-10, M: +/-20, Z: +80/-20)	Rating (X5R / X7R < 80%, Y5V/Y5U/Z5U < 1/3)	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
SCD1U10V2MX-1	0.1uF	M/X5R	10V	0402
SC10U6D3V5MX	10uF	M/X5R	6.3V	0805
SC2D2U16V5ZY	2.2uF	Z/Y5V	16V	0805

The naming rule is
Capacitor type + value + rating + size + tolerance + material
SCD1U10V2MX-1
SC=> SMT Ceramic, TC=> POS cap or SP cap
D1U => 0.1uF
10V => the voltage rating is 10V
2=> 0402, 3=>0603, 5=>0805
M=>tolerance J, K, M, Z
X=> X7R/X5R, Y=> Y5V
-1 => symbol version, nonsense to EE characteristic

BOM

緯創資通 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title ATI M5X-P POWER SEQUENCE		
Size A3	Document Number AG3	Rev 2
Date: Thursday, April 20, 2006		
Sheet 49 of 55		



The diagram shows the timing of various signals for the M56P device. The signals are organized into groups, with their values and timing relative to a common clock signal (47.51) indicated. The signals are color-coded: red for address/data, blue for control, and green for clock. The diagram is labeled 'M56P' at the top.

Signal	Value	Timing
MAB8	8	1
MAB11	7	2
MAB6	6	3
MAB7	5	4
MAB1	1	1
MAB2	7	2
MAB10	6	3
MAB5	5	4
MAB9	7	1
MAB0	7	2
MAB3	6	3
MAB4	5	4
B BA0	R	1
B A1	R376	1
MAB12_14	R368	1
47 ODTB0	ODTB0	R420
47.51 ODTB1	ODTB1	R374
47 RASB0#	RASB0#	R404
47.51 CASB0#	RASB1#	R375
47.51 CASB1#	CASB0#	R406
47 WEB0#	CASB1#	R372
47.51 WEB1#	WEB0#	R418
47 CSB0_0#	WEB1#	R370
47.51 CSB1_0#	CSB0_0#	R405
47 CKEB0	CSB1_0#	R373
47.51 CKEB1	CKEB0	R414
	CKEB1	R371

**FOR M56P AT DDR2 MEMORY SPEEDS ABOVE 350MHZ
MEMORY CONTROL SIGNALS WE,CAS,RAS,CS,CKE,ODT
AND MEMORY ADDRESS SIGNALS REQUIRE 55 OHM PULLUP
TO A VTT RAIL (50% OF VDDQ)**

47 CLK0 >>> CLK0

47 CLK0# >>> CLK0#

47.51 RDQS[7..0] >>> RDQS[7..0]

47.51 DQMB[7..0] >>> DQMB[7..0]

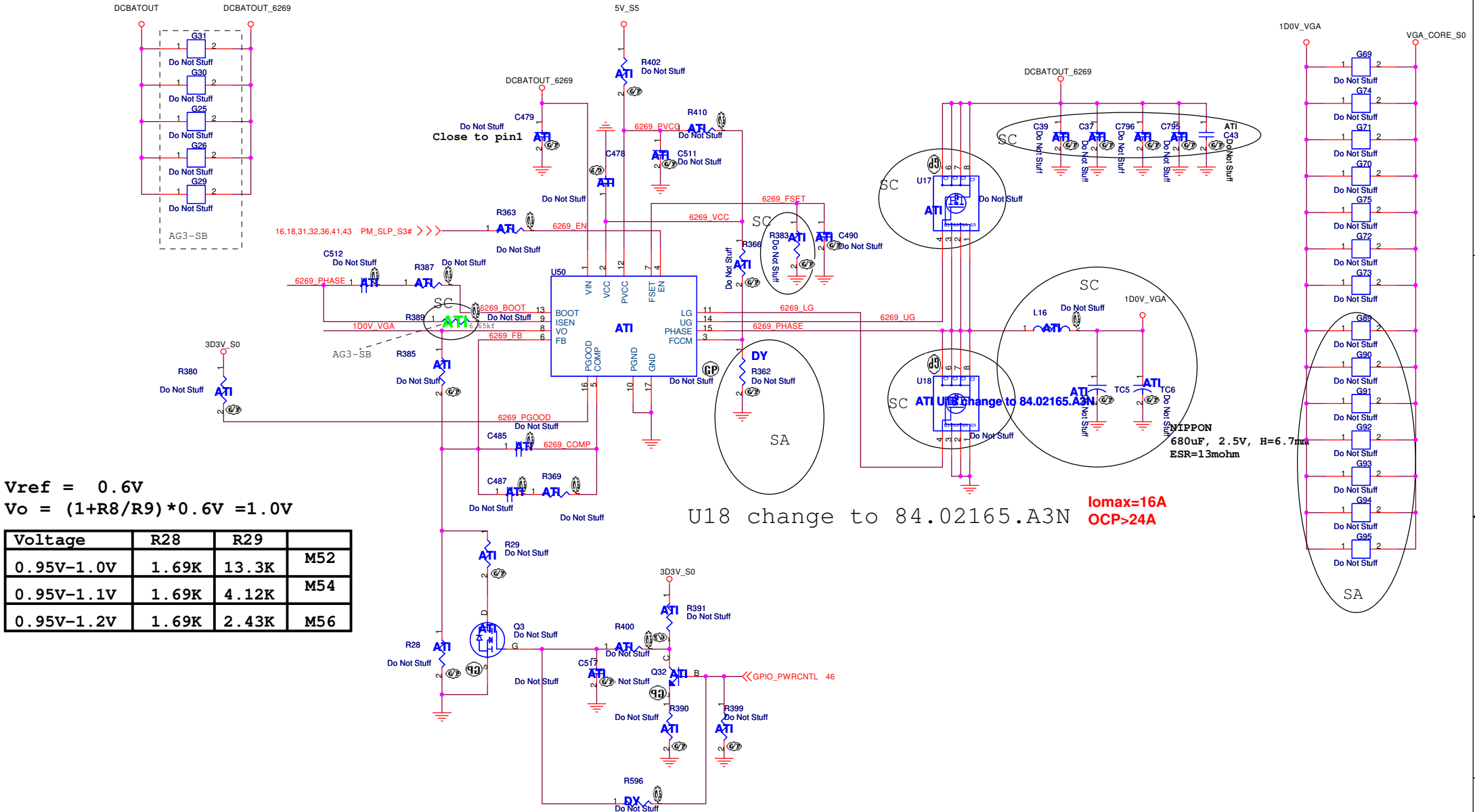
47.51 MDB[63..0] >>> MDB[63..0]

47.51 MAB[11..0] >>> MAB[11..0]

47.51 WDQS[7..0] >>> WDQS[7..0]

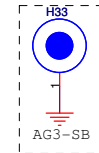
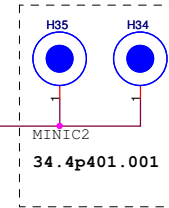
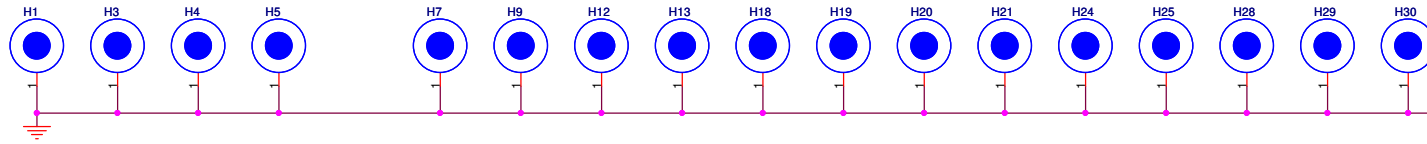
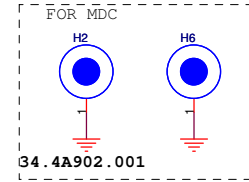
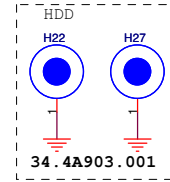
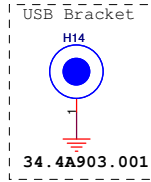
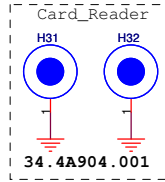
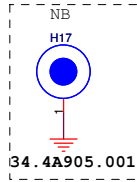
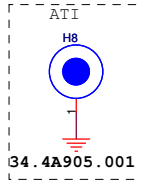
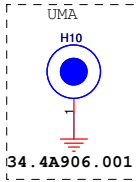
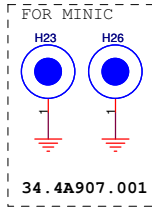
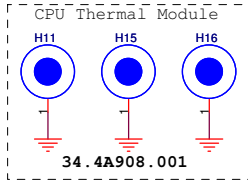
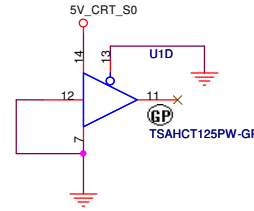
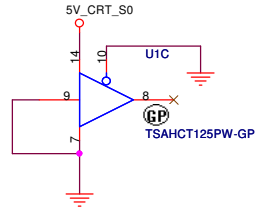
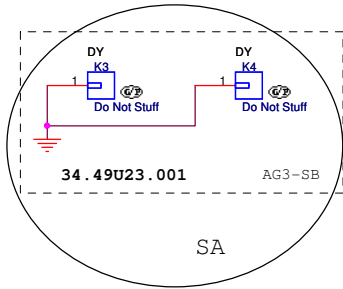
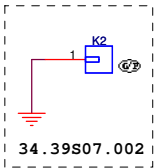
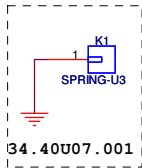
緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
VRAM 1/2			
Size	Document Number		Rev
A3	AG3		2
Date:	Thursday, April 20, 2006	Sheet	50 of 55



Vref = 0.6V
Vo = (1+R8/R9)*0.6V = 1.0V

Voltage	R28	R29	
0.95V-1.0V	1.69K	13.3K	M52
0.95V-1.1V	1.69K	4.12K	M54
0.95V-1.2V	1.69K	2.43K	M56



BOM

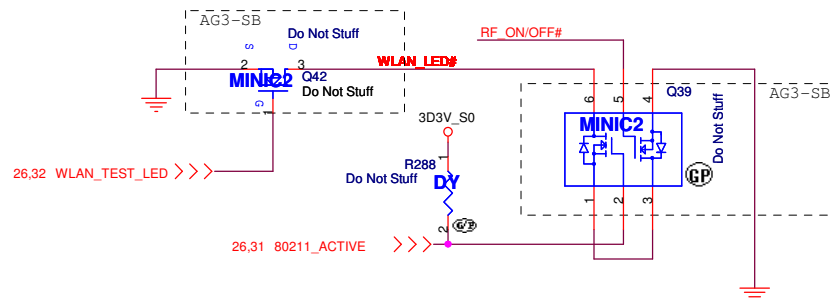
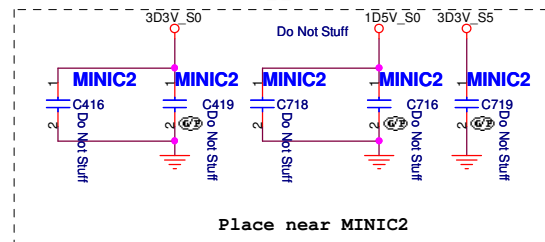
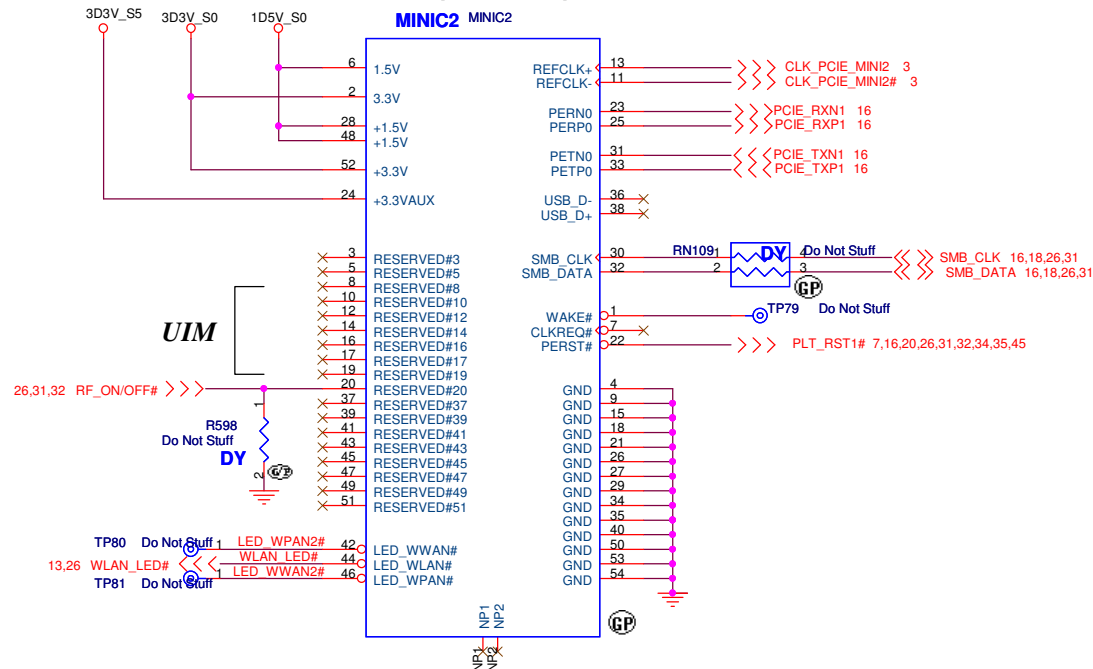
緯創資通 Wistron Corporation		
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title		
SPRING & BOSS		
Size A3	Document Number AG3	Rev 2
Date: Friday, April 21, 2006		Sheet 53 of 55

EMI CAP

AG3-SB



Mini Card Connector



BOM

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title MINICARD 2		
Size B	Document Number AG3	Rev 2
Date: Thursday, April 20, 2006	Sheet 55 of	55